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# **EE5323 HOMEWORK #3:CHARACTERIZING FINFET ASAP 7NM**

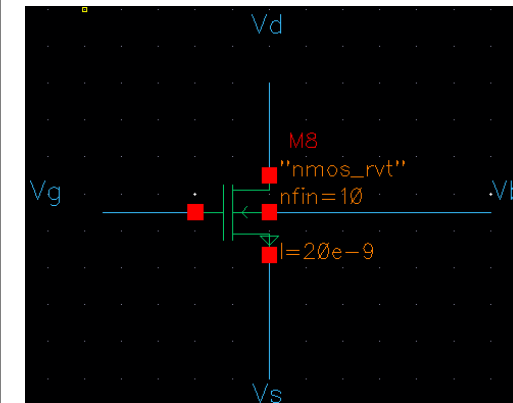
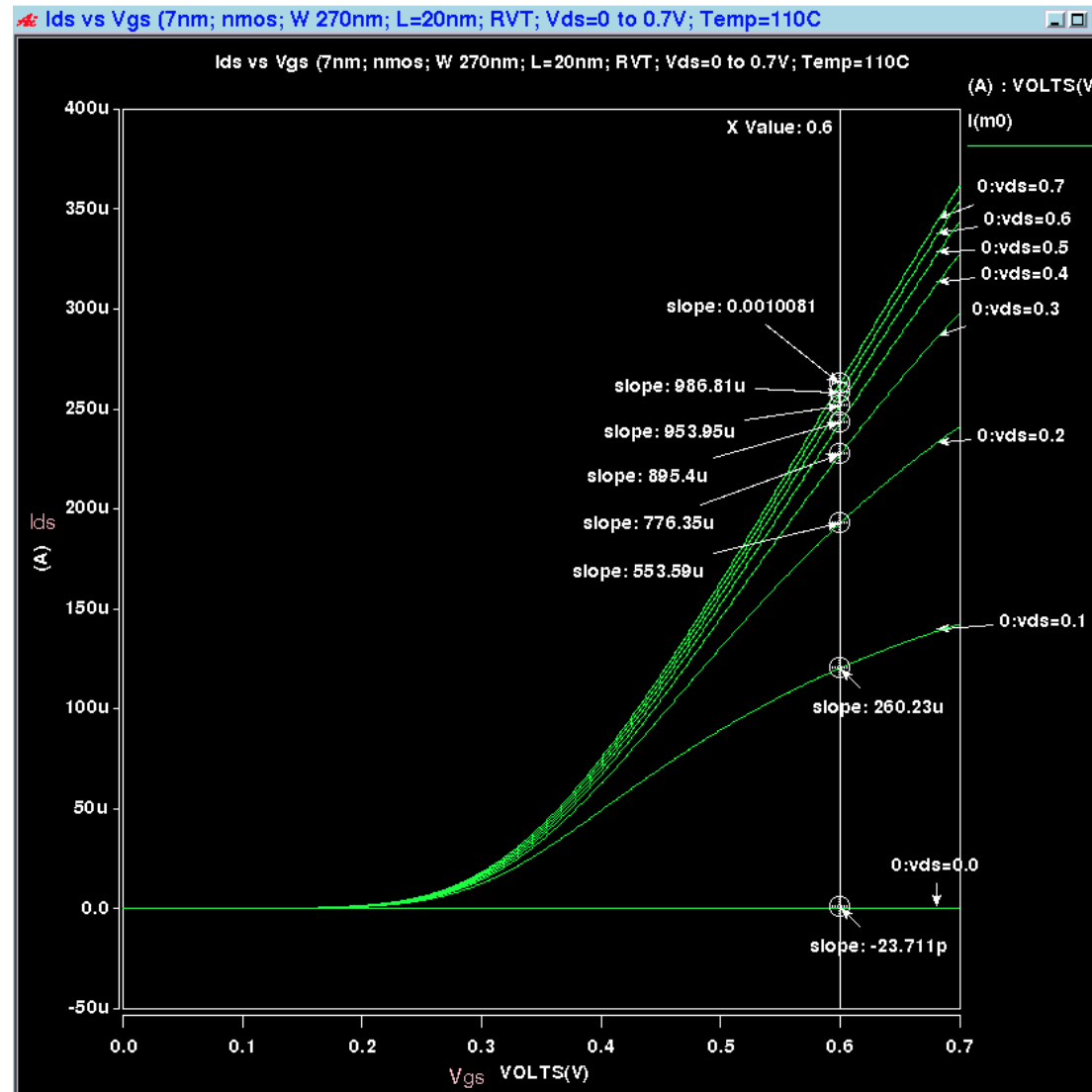
KARTHESHWAR SHANMUGA SUNDARAM

5569005



# IDS VERSUS VGS (FOR DIFFERENT VDS) -NMOS

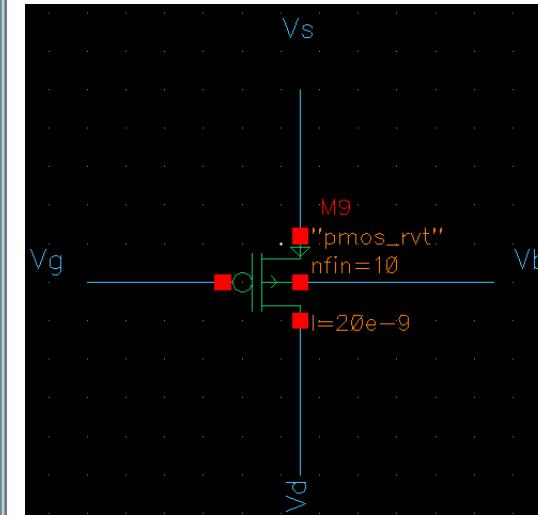
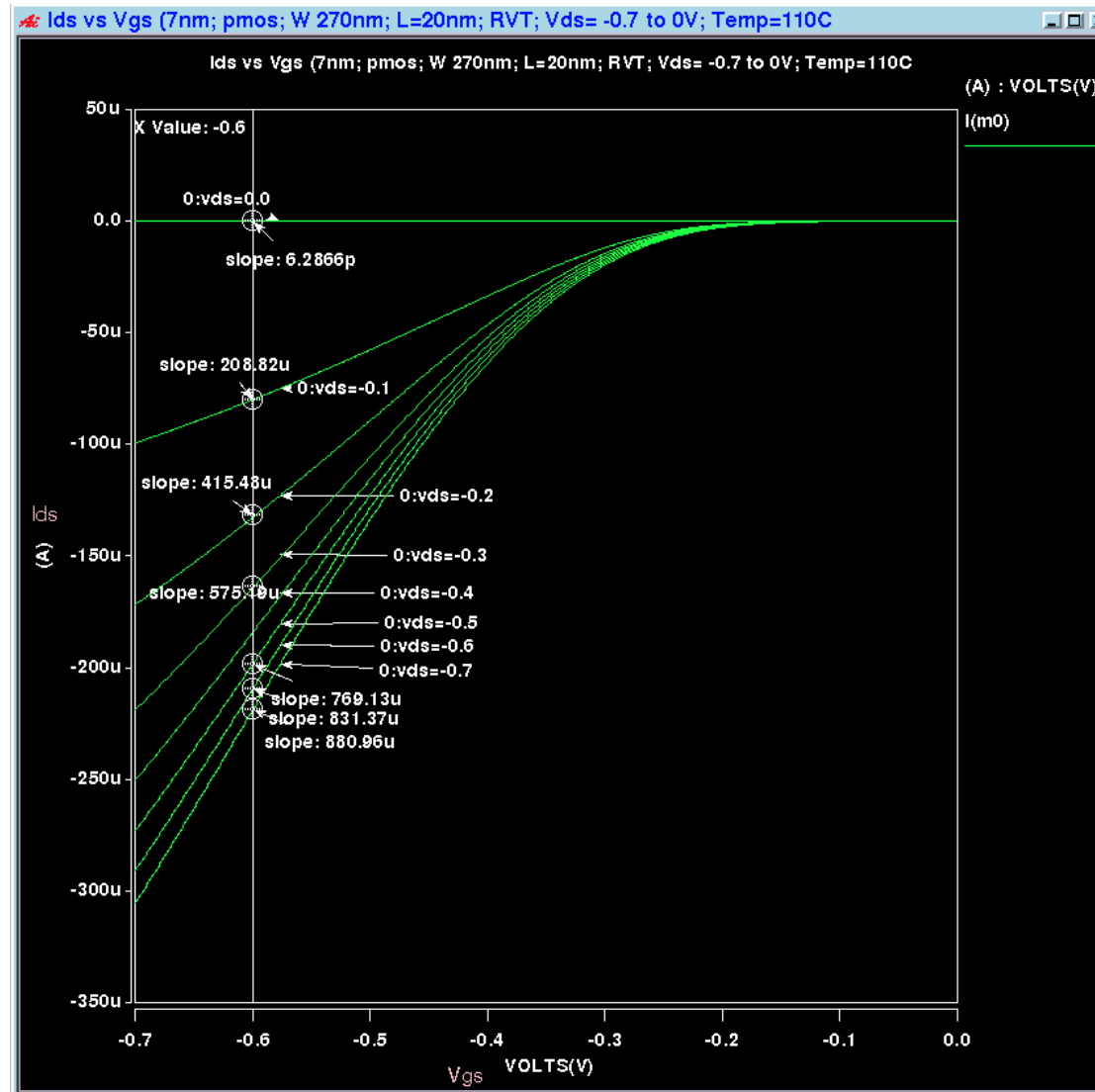
- For short channel devices  $I_{ds}$  is proportional to  $(V_{gs} - V_t - V_{dsat}/2)$
- The current below  $V_{gs} = V_t$  in linear scale is negligible and after  $V_t$  there is a linear relation to  $V_{gs}$
- As the  $V_{ds}$  increases the current increases as shown in graph



$V_s=0$ ,  $V_b=0$ ,  
 $V_d=0-0.7$  in steps of 0.1,  
 $V_g=0-0.7$  in steps of 0.001

# IDS VERSUS VGS (FOR DIFFERENT VDS) - PMOS

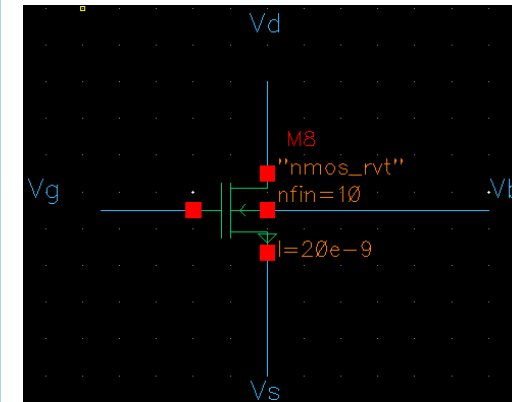
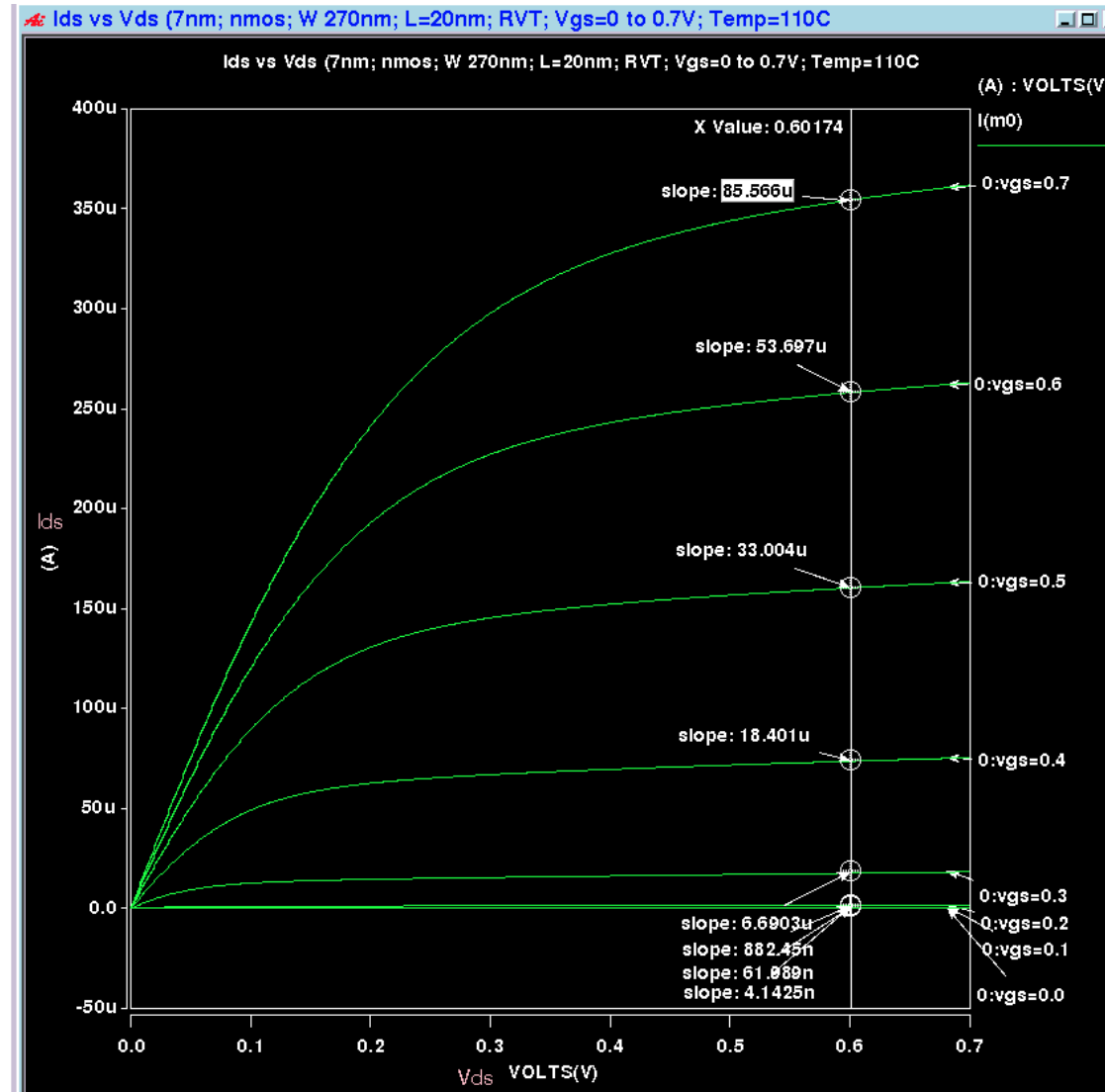
- For short channel devices  $I_{ds}$  is proportional to  $(V_{gs} - V_t - V_{dsat}/2)$
- The current below  $V_t$  in linear scale is negligible and after  $V_t$
- As the  $V_{ds}$  increases the current increases as shown in graph
- As compared to nmos the pmos current is little lower, say for  $V_{ds}=0.7V$  the pmos current is  $300\mu A$  but nmos current is  $350\mu A$ , this is due to higher mobility of nmos.



Vs=0 , Vb=0  
Vd = 0 to -0.7 in steps of -0.1  
Vg= 0 to -0.7 in steps of -0.001

# IDS VERSUS VDS (FOR DIFFERENT VGS)- NMOS

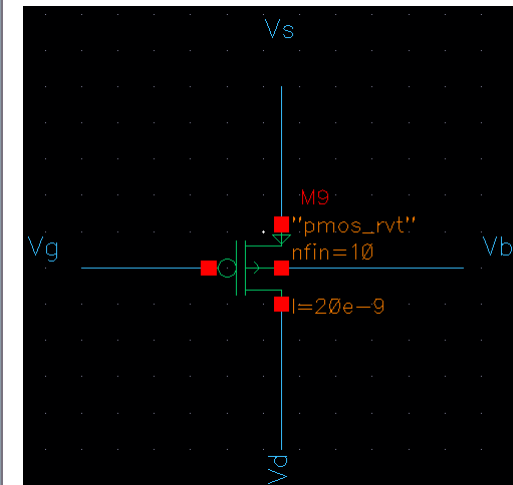
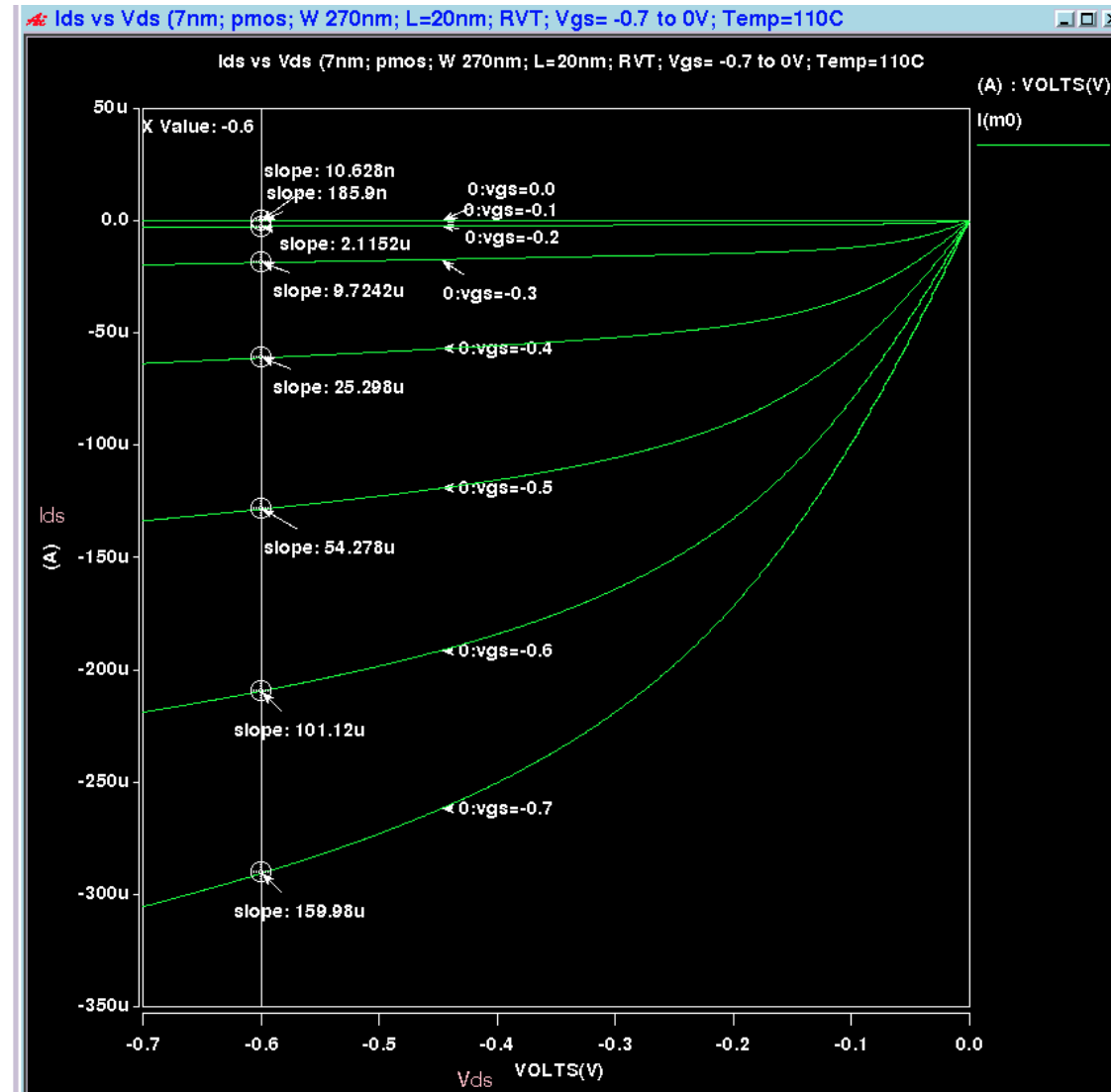
- For a given  $V_{gs}$  as  $V_{ds}$  increases the current increases
- For short channel devices  $I_{ds}$  is proportional to  $(V_{gs} - V_t - V_{dsat}/2)$



$V_s=0$ ,  $V_b=0$ ,  
 $V_d = 0$  to  $0.7$  in steps of  $0.001$ ,  
 $V_g = 0$  to  $0.7$  in steps of  $0.1$

# IDS VERSUS VDS (FOR DIFFERENT VGS)- PMOS

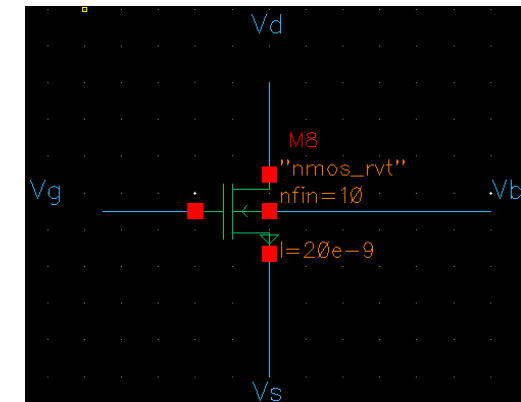
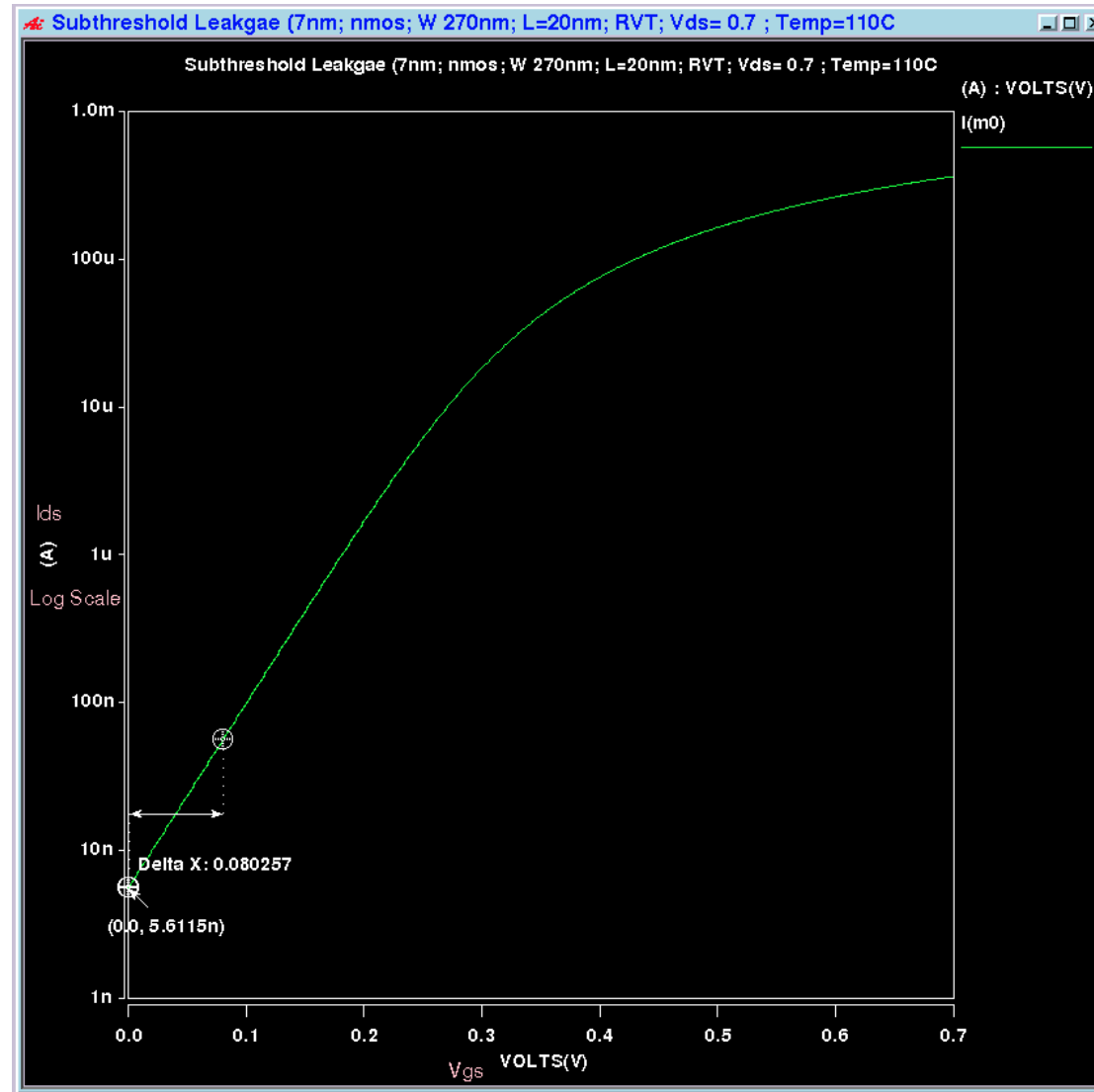
- For a given  $V_{gs}$  as  $V_{ds}$  increases the current increases
- For short channel devices  $I_{ds}$  is proportional to  $(V_{gs} - V_t - V_{dsat}/2)$
- As compared to nmos the pmos current is little lower, say for  $V_{ds}=0.7V$  the pmos current is  $300\mu A$  but nmos current is  $350\mu A$ , this is due to higher mobility of nmos.



$V_s=0$ ,  $V_b=0$ ,  
 $V_d = -0.7$  to  $0$  in steps of  $0.001$ ,  
 $V_g = -0.7$  to  $0$  in steps of  $0.1$

# SUB-THRESHOLD SWING [V/DEC]- NMOS

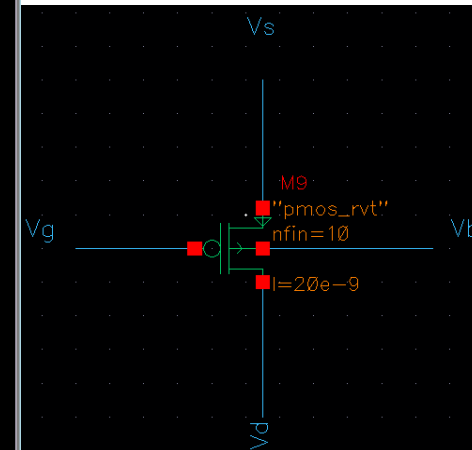
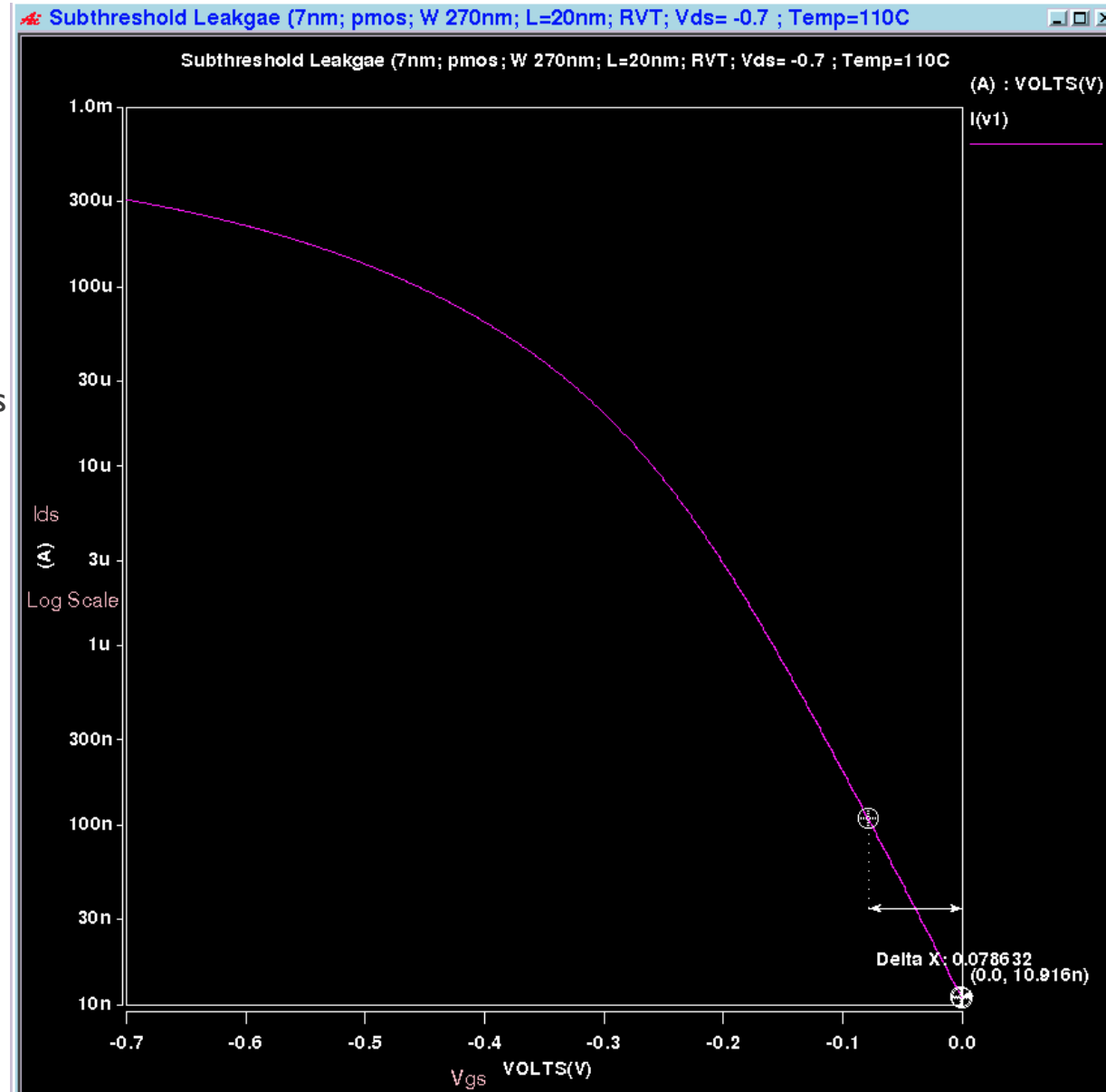
- Subthreshold current is the current when transistor is off and MOS behaves as BJT
- $I_{ds} = \exp(V_{gs}-v_t/(mkT/q))$
- As shown in graph current is plotted in log scale and below  $V_t$  there is a linear relation.
- $m=1$  for Finfet and operating temperature is 110deg.
- The Sub threshold swing is given as  $(\ln 10 * m * k * T / q)$  which is current for a 10x change in voltage = 80 mV



$V_s=0, V_b=0,$   
 $V_d = 0.7$   
 $V_g= 0 \text{ to } 0.7 \text{ in steps of } 0.001$

# SUB-THRESHOLD SWING [V/DEC] - PMOS

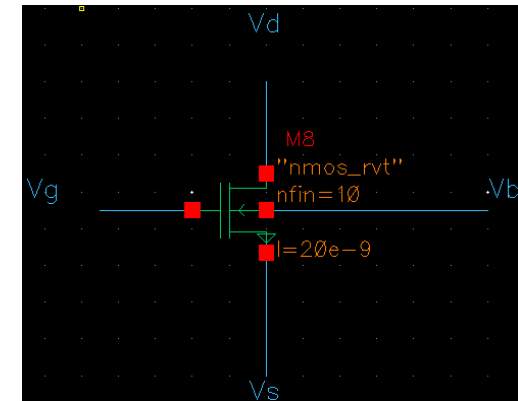
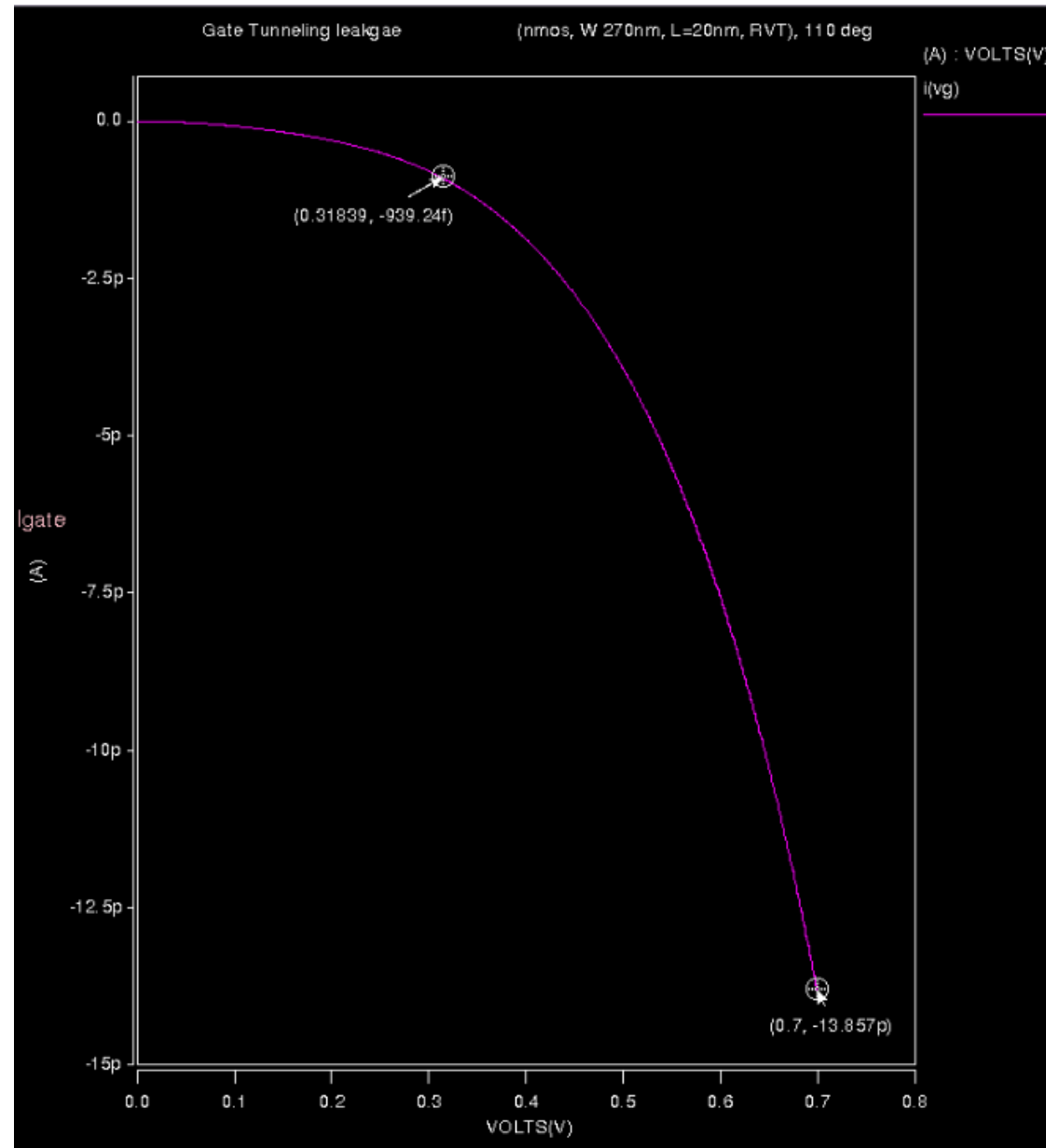
- Subthreshold current is the current when transistor is off and MOS behaves as BJT
- $I_{ds} = \exp(V_{gs}-v_t/(mkT/q))$
- As shown in graph current is plotted in log scale and below  $V_t$  there is a linear relation.
- $m=1$  for Finfet and operating temperature is 110deg.
- The Sub threshold swing is given as  $(\ln 10 * m * k * T / q)$  which is current for a 10x change in voltage = 78 mV
- The subthreshold swing for nmos and pmos are almost same.



$V_s=0, V_b=0,$   
 $V_d = -0.7$   
 $V_g = -0.7$  to 0 in steps of 0.001

# GATE TUNNELING LEAKAGE VERSUS VDD -NMOS

- Gate tunneling is maximum for ON device
- It is 3-10 times higher than pmos gate leakage
- It is strong function of ( $V_{ox}/t_{ox}$ ).
- So as  $V_g$  increases then there is exponential increase as seen in the graph

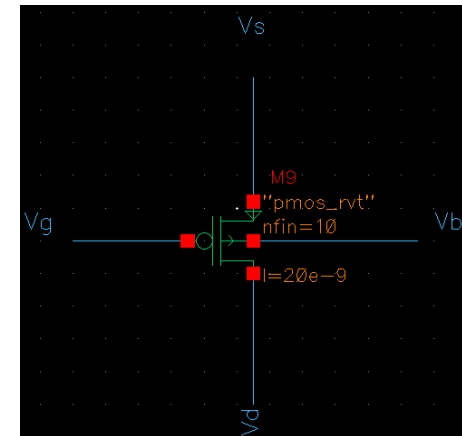
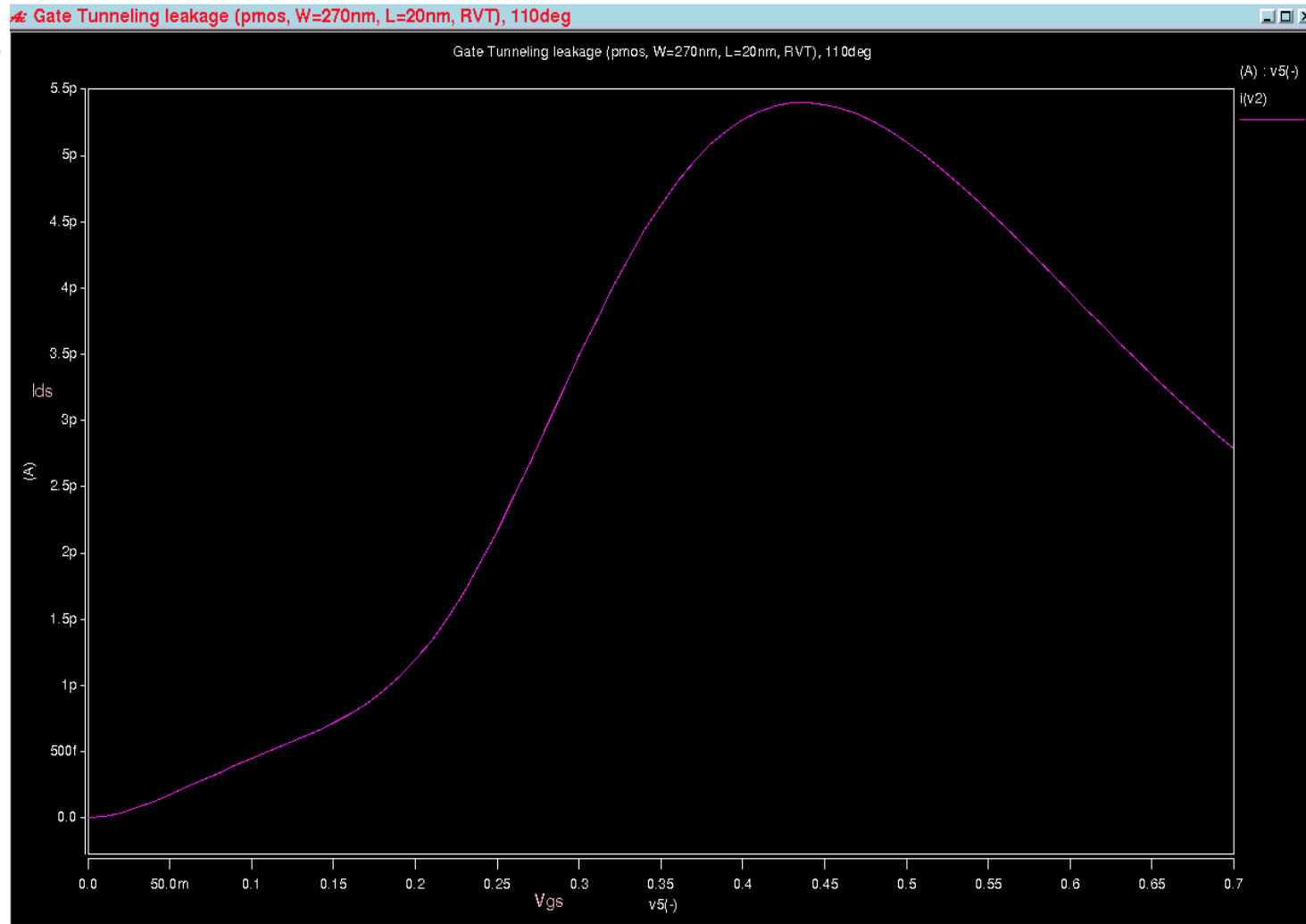


$V_s=0$ ,  $V_b=0$ ,  
 $V_d = 0$   
 $V_g= 0$  to 0.7 in steps of 0.001



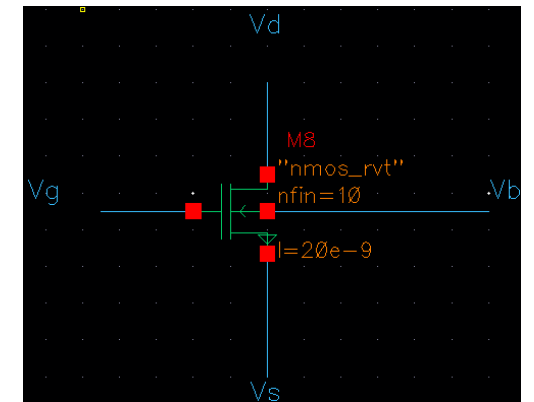
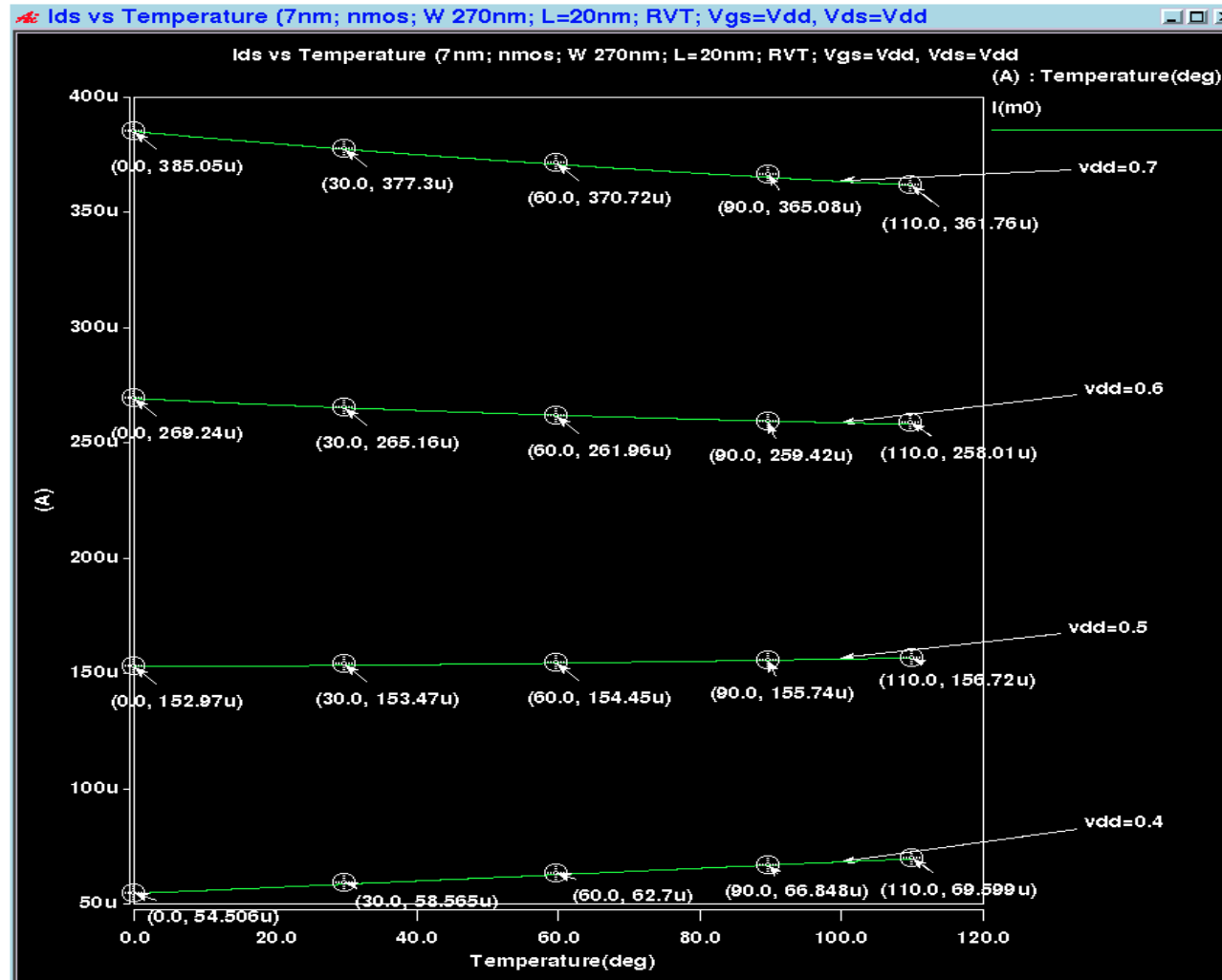
# GATE TUNNELING LEAKAGE VERSUS VDD - PMOS

- Pmos the maximum gate leakage current is 5pA which is approximately 3 times lesser than nmos gate leakage



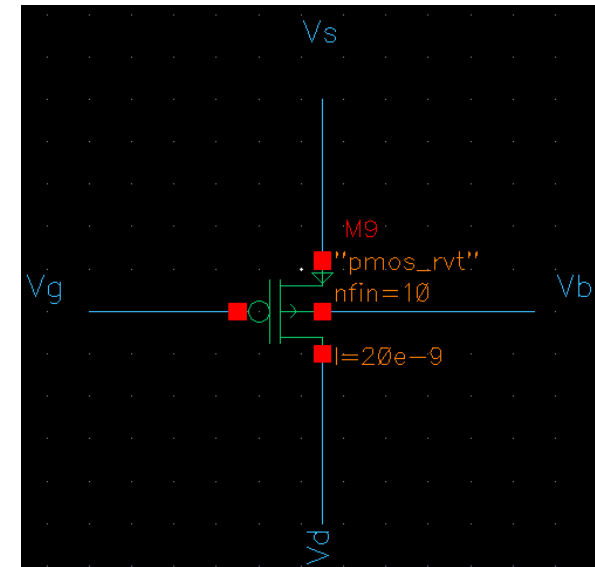
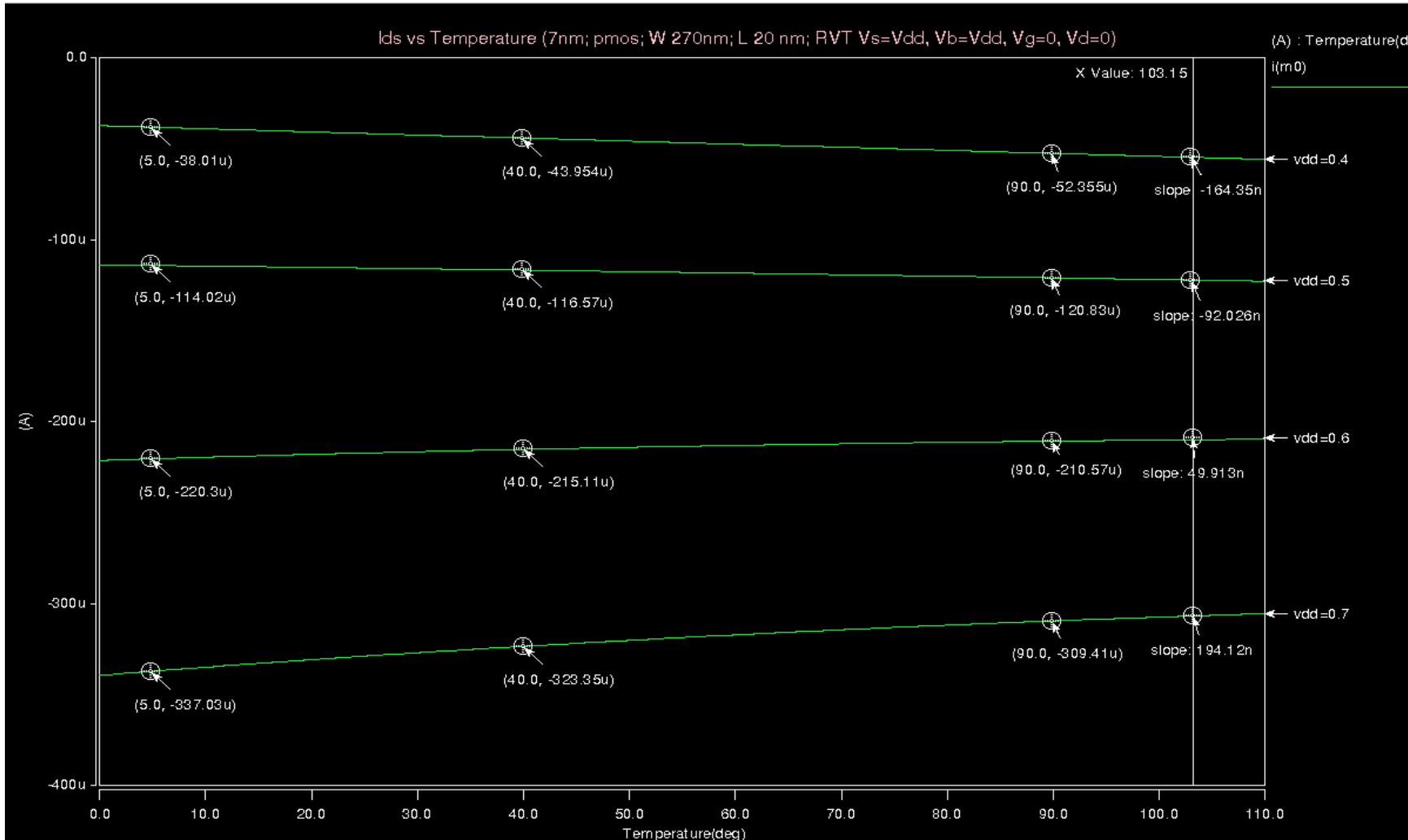
Vs=0 to 0.7 in steps of 0.001,  
Vb=0 to 0.7 in steps of 0.001,  
Vd = 0 to 0.7 in steps of 0.001  
Vg= 0

# IDS (VGS=VDS=VDD) VERSUS TEMPERATURE (0C ~ 110C), FOR VDD=0.7V, 0.6V, 0.5V, 0.4V - NMOS



Vs=0, Vb=0,  
Vd = 0.4 0.7 in steps of 0.1  
Vg= 0.4 0.7 in steps of 0.1  
temperature sweep from: 0-110 in steps of 0.5

# IDS (VGS=VDS=VDD) VERSUS TEMPERATURE (0C ~ 110C), FOR VDD=0.7V, 0.6V, 0.5V, 0.4V - PMOS



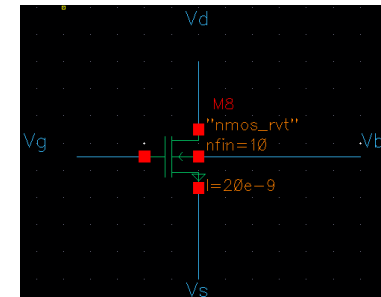
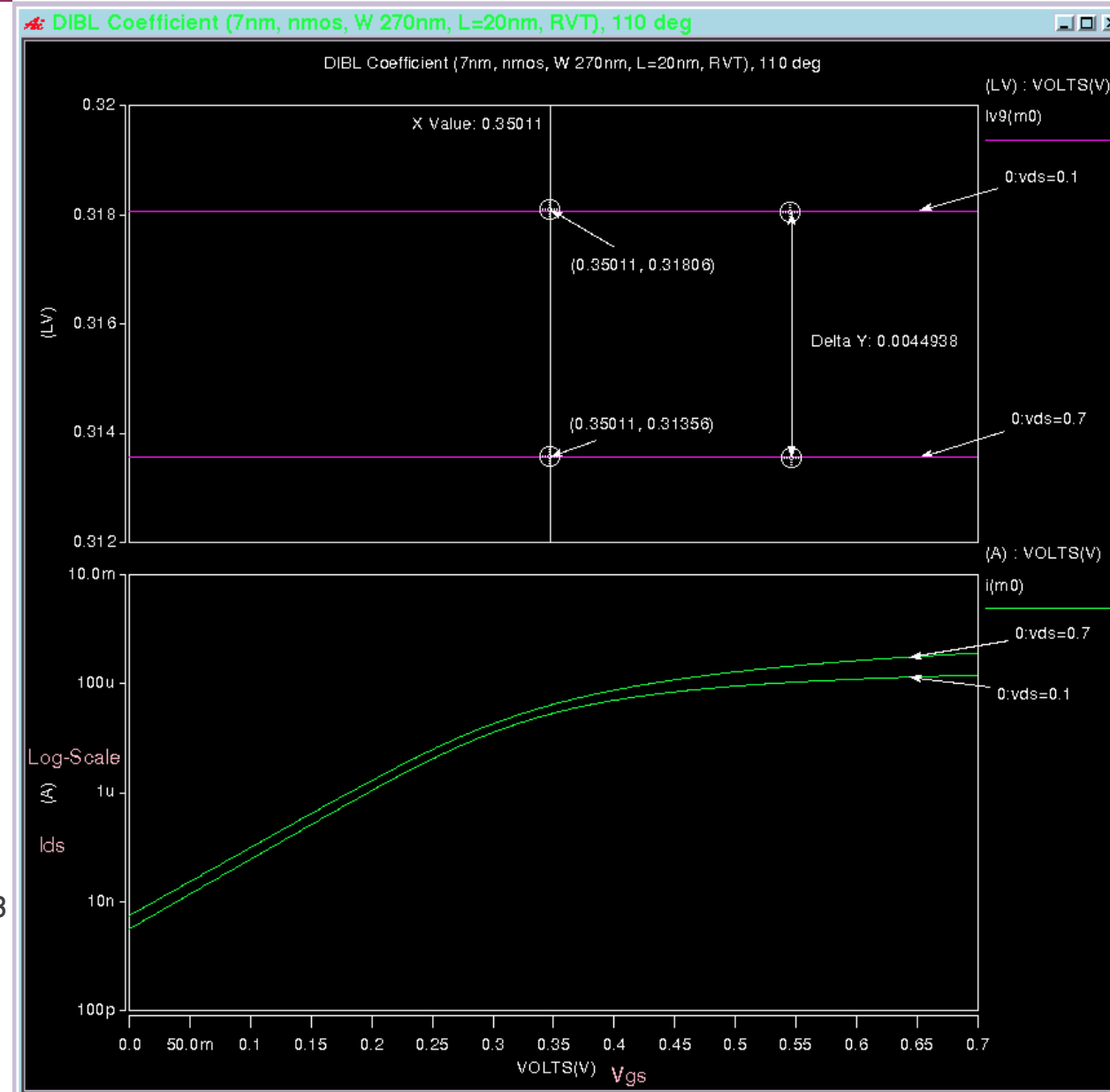
Vs=0.4 0.7 in steps of 0.1  
 Vb=0.4 0.7 in steps of 0.1  
 Vd = 0, Vg= 0  
 temperature sweep from: 0-110 in steps of 0.5

# TEMPERATURE DEPENDENCE

- As temperature increases
  - Mobility decreases (scattering effect)  $\Rightarrow$   $I_{ds}$  decreases
  - Threshold voltage increase  $\Rightarrow$   $I_{ds}$  increases
- Based on the operating voltage either of the two phenomenon takes place
- If transistor is operating at region closer to  $V_t$  then  $V_t$  effect dominates  $\Rightarrow$  for higher temperature there is more current
- If transistor is operating at a higher voltage then mobility dominates  $\Rightarrow$  for higher temperature the current is lesser
- This behavior is clearly seen in the graph show in in previous two slides
- For  $V_{dd}$  of 0.7, 0.6 current is reducing as temperature increases
- For  $V_{dd}$  of 0.4, 0.5 current is increasing as temperature increases
- The dependance of temperature is same for both nmos and pmos

# DIBL COEFFICIENT [V/V] - NMOS

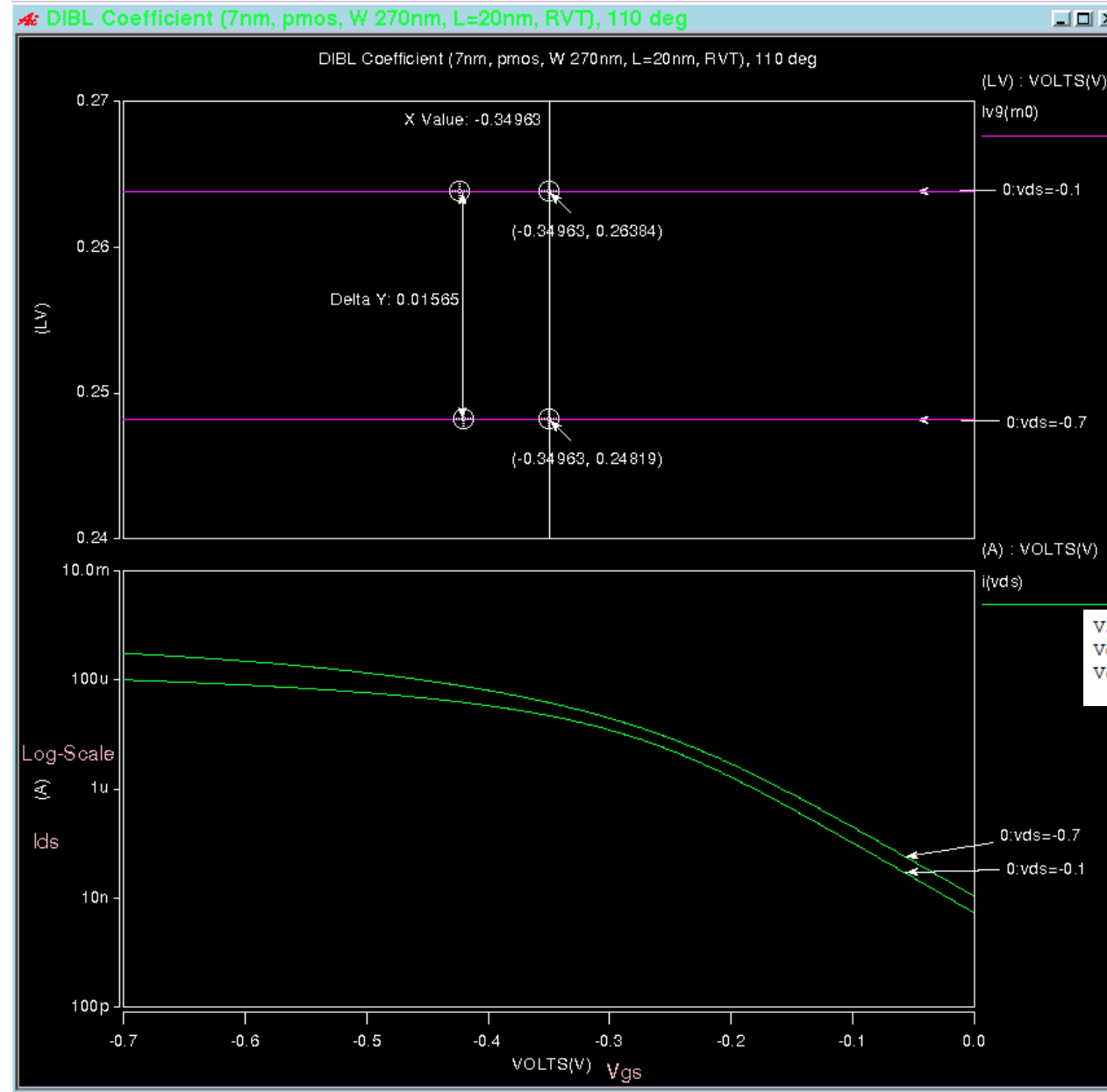
- DIBL refers to Drain Induced barrier lowering; it refers to lowering of  $V_t$  on increased  $V_d$  (because of increasing depletion layer width)
- $V_t = V_{t0} - (\tilde{n})V_d$  where  $\tilde{n}$  is dibl coefficient
- As seen from the curve as  $V_d$  is increased  $V_t$  has reduced.
- $V_t$  for  $V_d=0.7V$  is 0.31356V
- $V_t$  for  $V_d=0.1V$  is 0.31806V
- $Lv9(mo)$  shows the  $V_t$  value
- $I_{ds}$  vs  $V_{gs}$  (logscale) is plotted and the curve has shifted as shown in fig.
- DIBL coefficient for nmos from figure is obtained as  $(\Delta V_t)/(\Delta V_d) = 0.0044/0.6 = 0.0073$



$V_s=0$ ,  $V_b=0$ ,  
 $V_d = 0.1, 0.7$   
 $V_g = 0.7$  in steps of 0.001

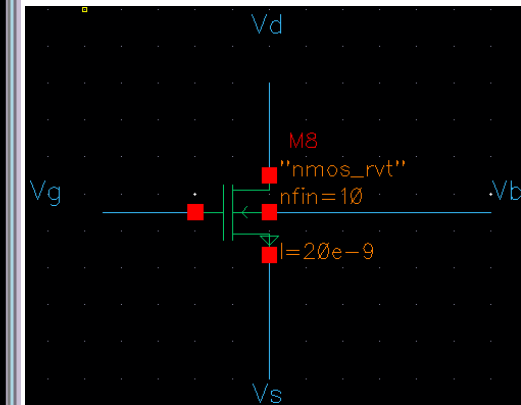
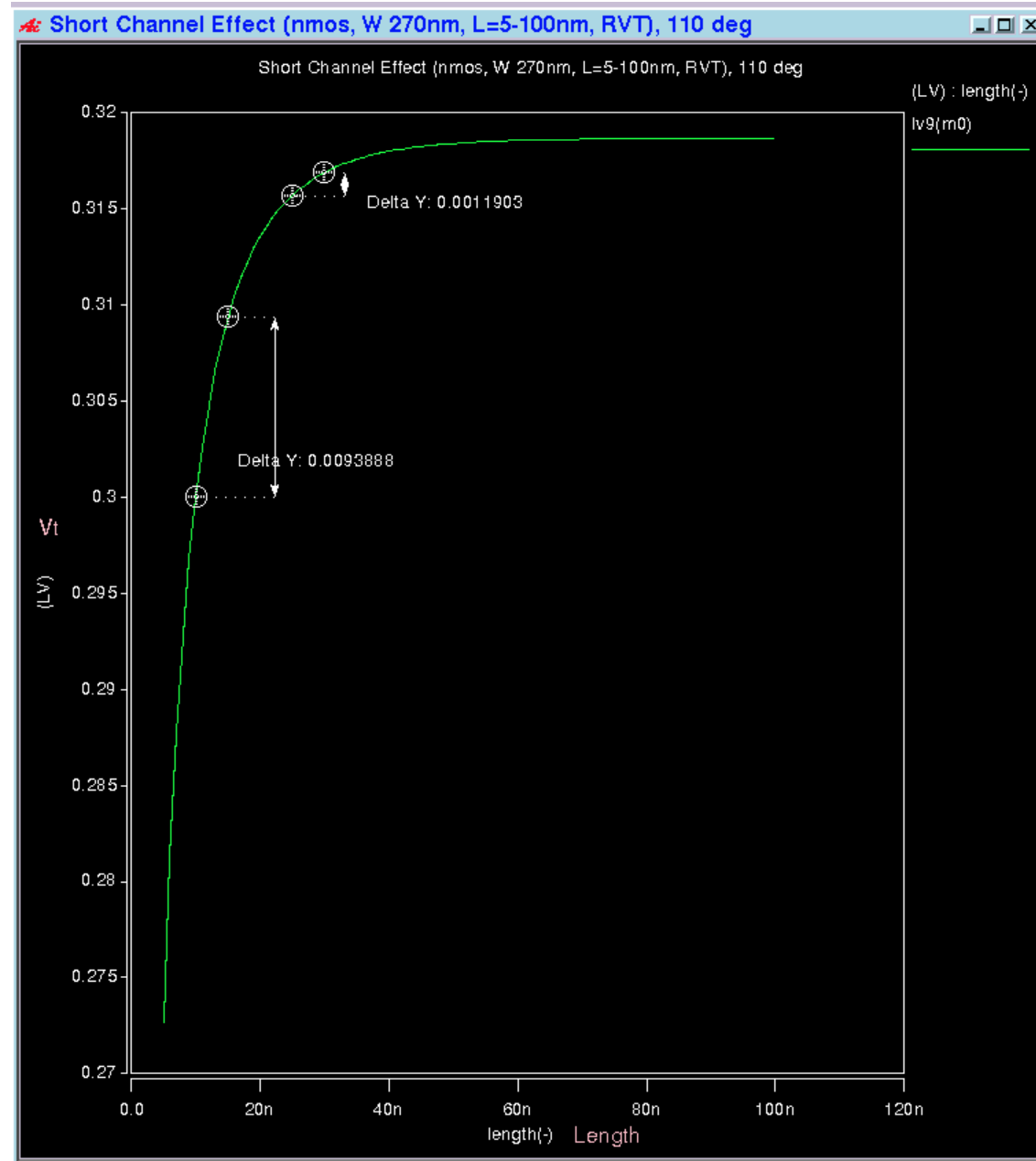
# DIBL COEFFICIENT [V/V] - PMOS

- DIBL refers to Drain Induced barrier lowering; it refers to lowering of  $V_t$  on increased  $V_{ds}$  (because of increasing depletion layer width)
- $V_t = V_{t0} - (\tilde{n})V_{ds}$  where  $\tilde{n}$  is dibl coefficient
- As seen from the curve as  $V_{ds}$  is increased  $V_t$  has reduced.
- $V_t$  for  $V_{ds} = -0.7V$  is  $0.24819V$
- $V_t$  for  $V_{ds} = -0.1V$  is  $0.26384V$
- $Lv9(mo)$  shows the  $V_t$  value
- $I_{ds}$  vs  $V_{gs}$  is plotted and the curve has shifted as shown in fig.
- DIBL coefficient for pmos from figure is obtained as  $(\Delta V_t)/(\Delta V_{ds}) = 0.01565/0.6 = 0.02608$
- DIBL coefficient for pmos is higher as  $(\Delta V_t)$  for pmos is higher



# SHORT CHANNEL EFFECT - NMOS

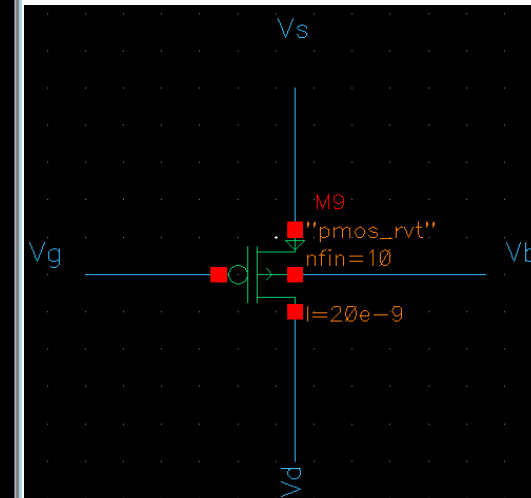
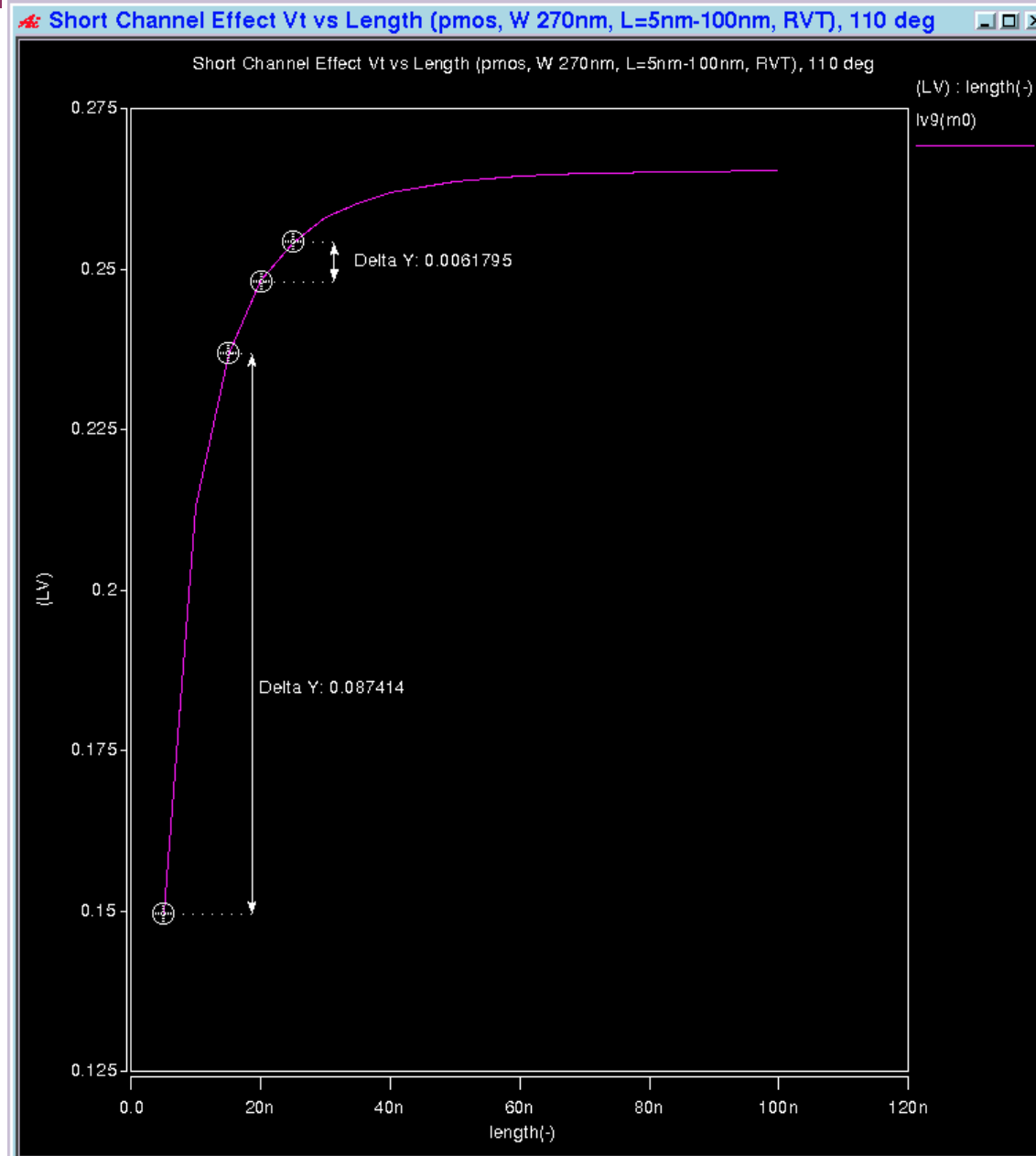
- Short channel effect refers to variation of  $V_t$  wrt length
- For ASAP 7nm PDK the channel length is 20 nm.
- As it can be seen as the length decreases (<20nm) the variation in  $V_t$  is very drastic ( Delta Y is more for same delta x) ie for a small change in length there is a large change in  $V_t$
- But for length greater than 20 nm there is not much variation



Vs=0, Vb=0,  
Vd = 0.7  
Vg= 0.7  
length sweep 5nm-100nm

# SHORT CHANNEL EFFECT - PMOS

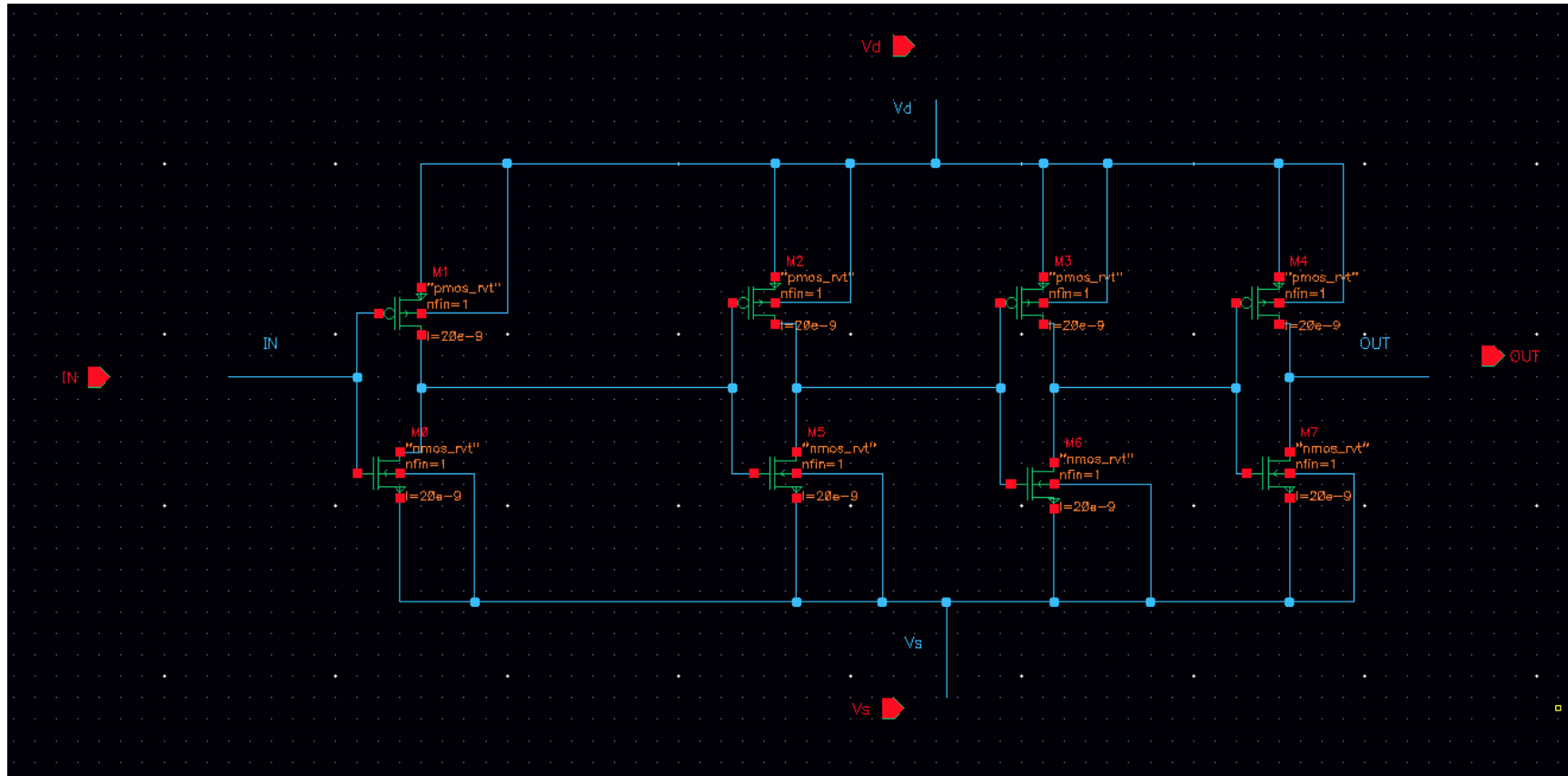
- Short channel effect refers to variation of  $V_t$  wrt length
- For ASAP 7nm PDK the channel length is 20 nm.
- As it can be seen as the length decreases (<20nm) the variation in  $V_t$  is very drastic (Delta Y is more for same delta x) ie for a small change in length there is a large change in  $V_t$
- But for length greater than 20 nm there is not much variation
- Short channel effect follows the same behavior for nmos and pmos



$V_s=0$  ,  $V_b=0.7$   
 $V_d = 0.7$   
 $V_g = 0$   
 length sweep 5nm-100nm



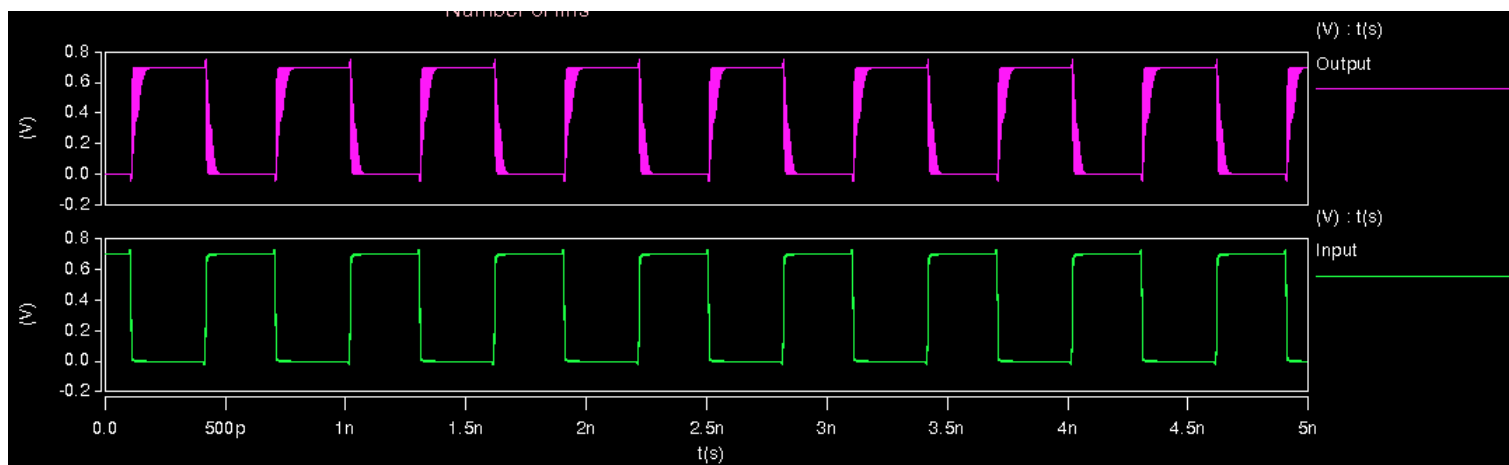
## 7. DELAY CHARACTERIZATION OF INVERTER - SCHEMATIC



- For characterizing delay of an inverter 4 inverters are placed.
- 1st inverter makes sure that input is a curve and not a step input
- 2nd inverter is the inverter to be characterized
- 3rd inverter acts as a load. Therefore the width of this 3rd inverter is changed to vary the load capacitance
- There is a 4th inverter kept to account for the miller effect of 3rd inverter

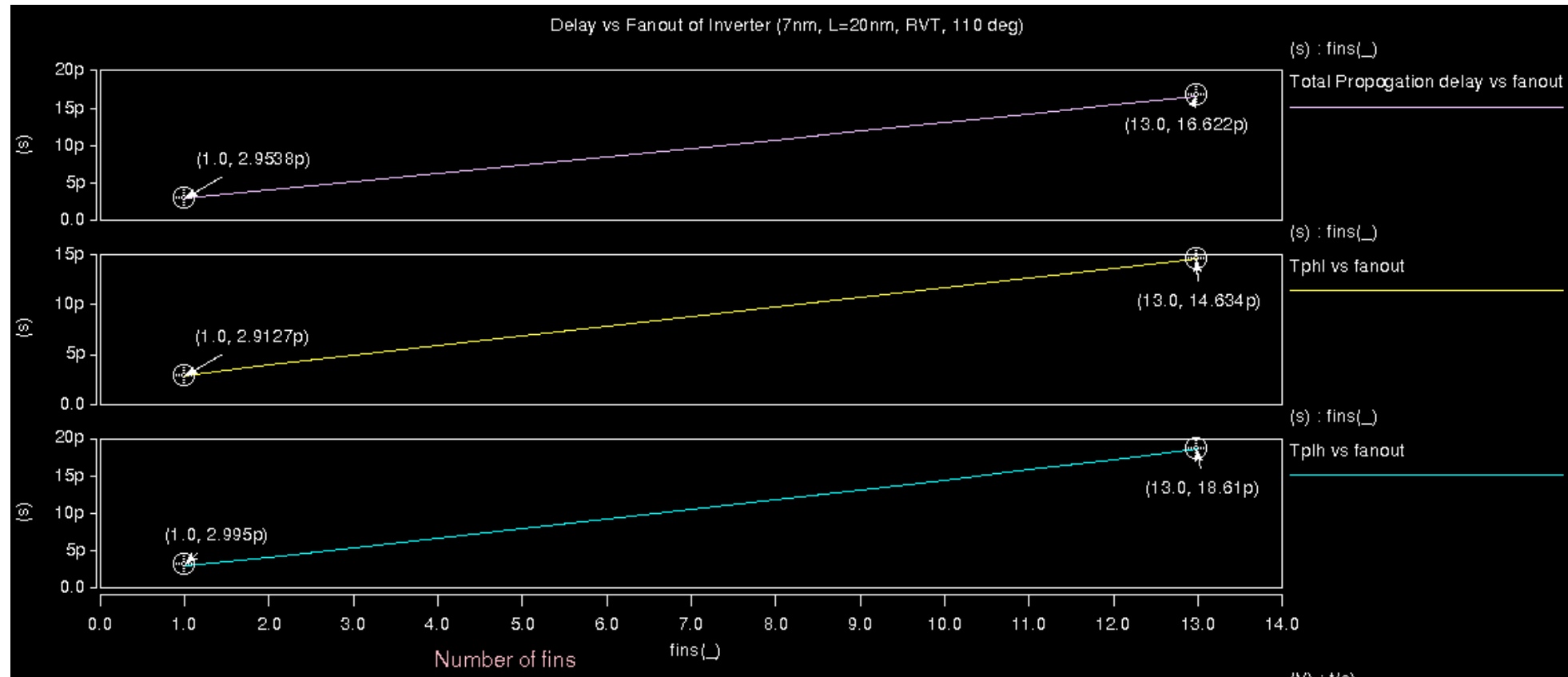
INPUT : INPUT OF 2ND INVERTER

OUTPUT: OUTPUT OF 2ND INVERTER FOR DIFFERENT FANOUTS



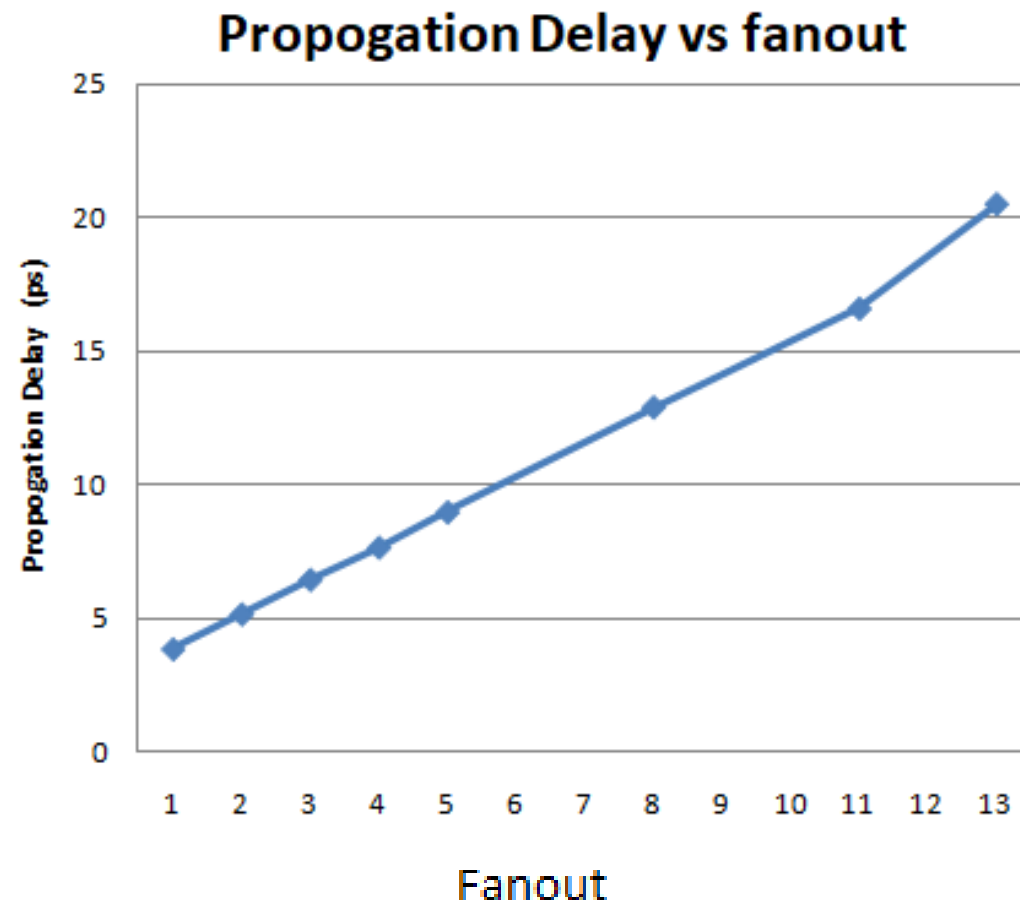
- As shown in previous slide the voltage given at
  - $V_d : V_{DD} = 0.7V$
  - $V_s : V_{SS} = 0V$
  - IN : Clock pulse with on time 300 ps, off time 300 ps
- Parameter width =  $8 \times 10^{-9} \times \text{fanout}$
- $\# \text{ Fin} = 3 \times \text{fanout}$
- Fanout is swept from 1 to 13

# DELAY (T PHL ,T PLH ,AND AVERAGE OF THE TWO) VERSUS FANOUT OF AN INVERTER- SCHEMATIC

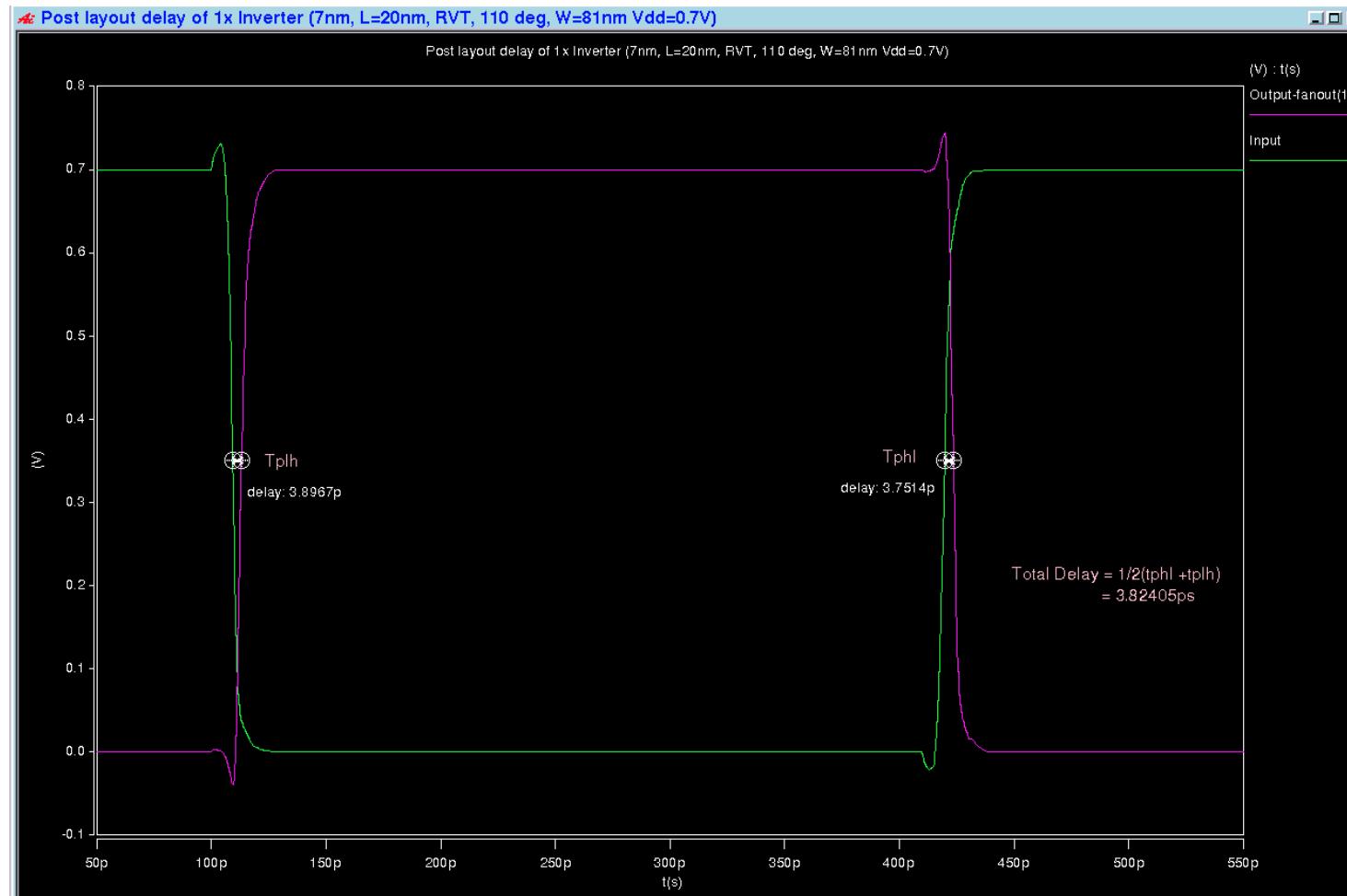


- Delay is a function of  $(R_{eff} * C_l) \ln 2$
- As the fanout increases the load capacitance increases
- Also  $t_p = t_{p0}(1 + f/\gamma)$
- Therefore we see delay vs fanout graph as a linear function
- $t_{plh}$  delay for a fanout of 1 inverter is 2.995 ps
- $t_{phl}$  delay for a fanout of 1 inverter is 2.9127 ps
- Total propagation delay is the average of two = 2.9538 ps

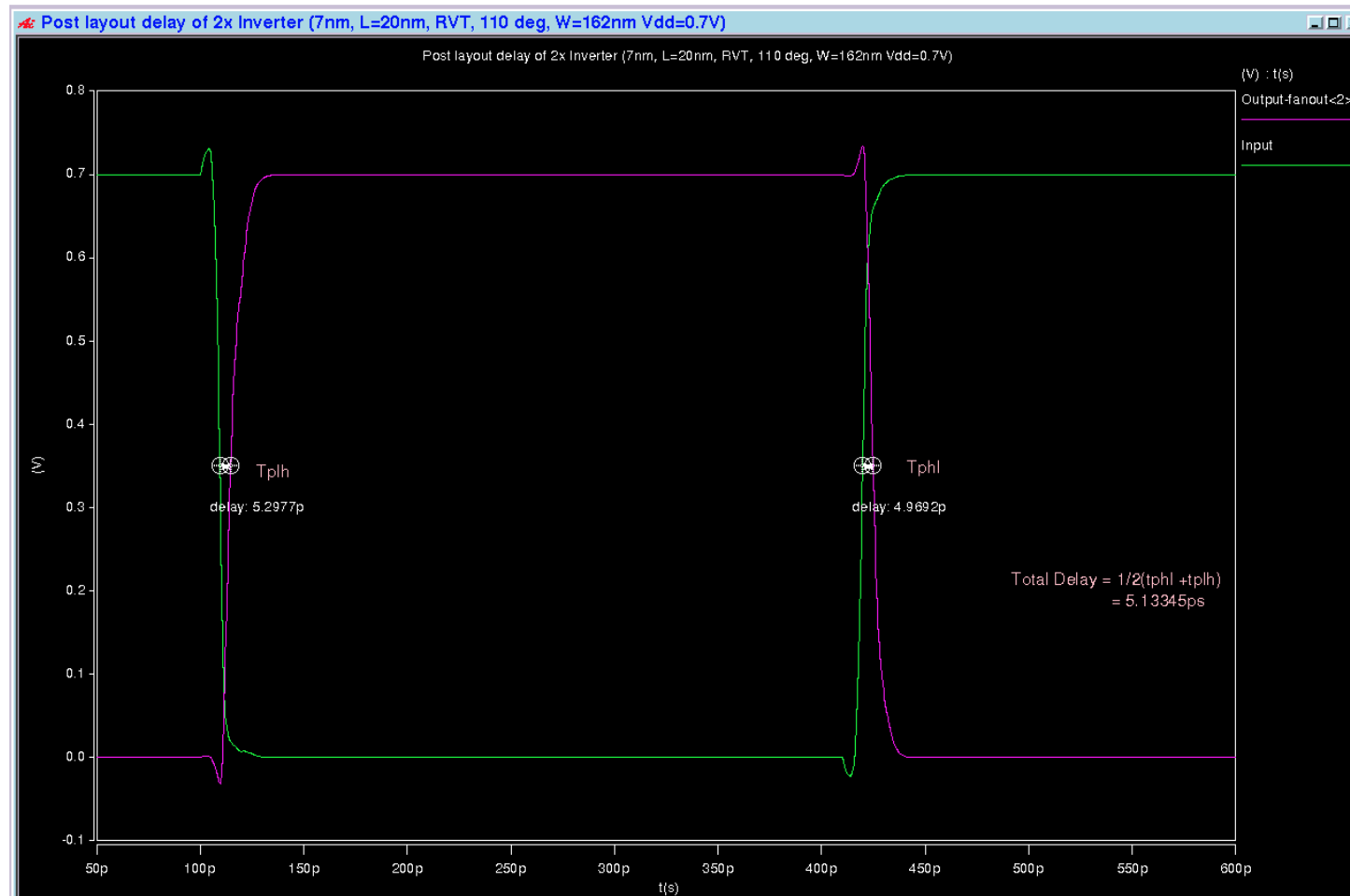
# LAYOUT- DELAY VS FANOUT



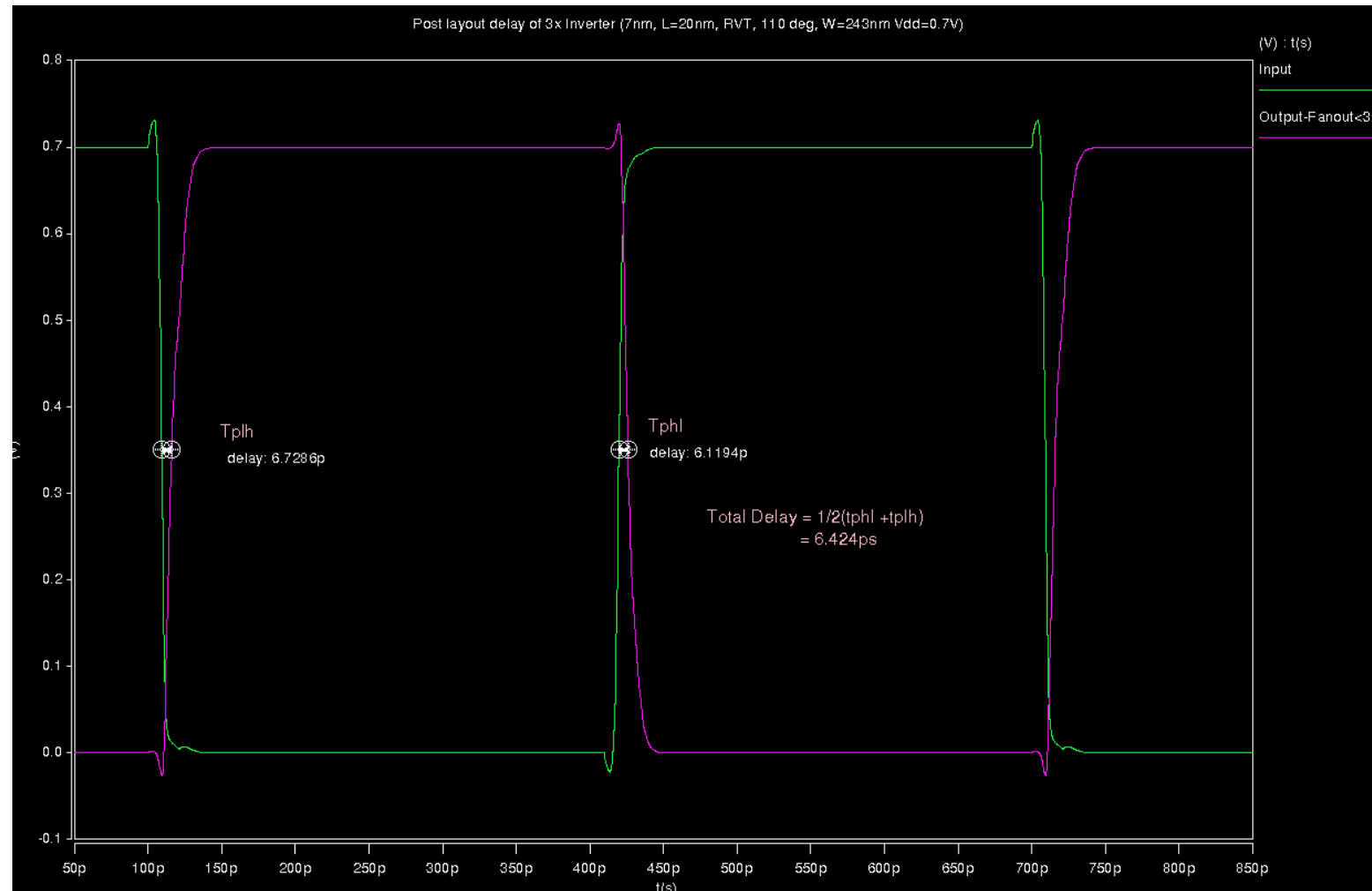
# DELAY FOR 1X INVERTER- LAYOUT



# DELAY FOR 2X INVERTER- LAYOUT

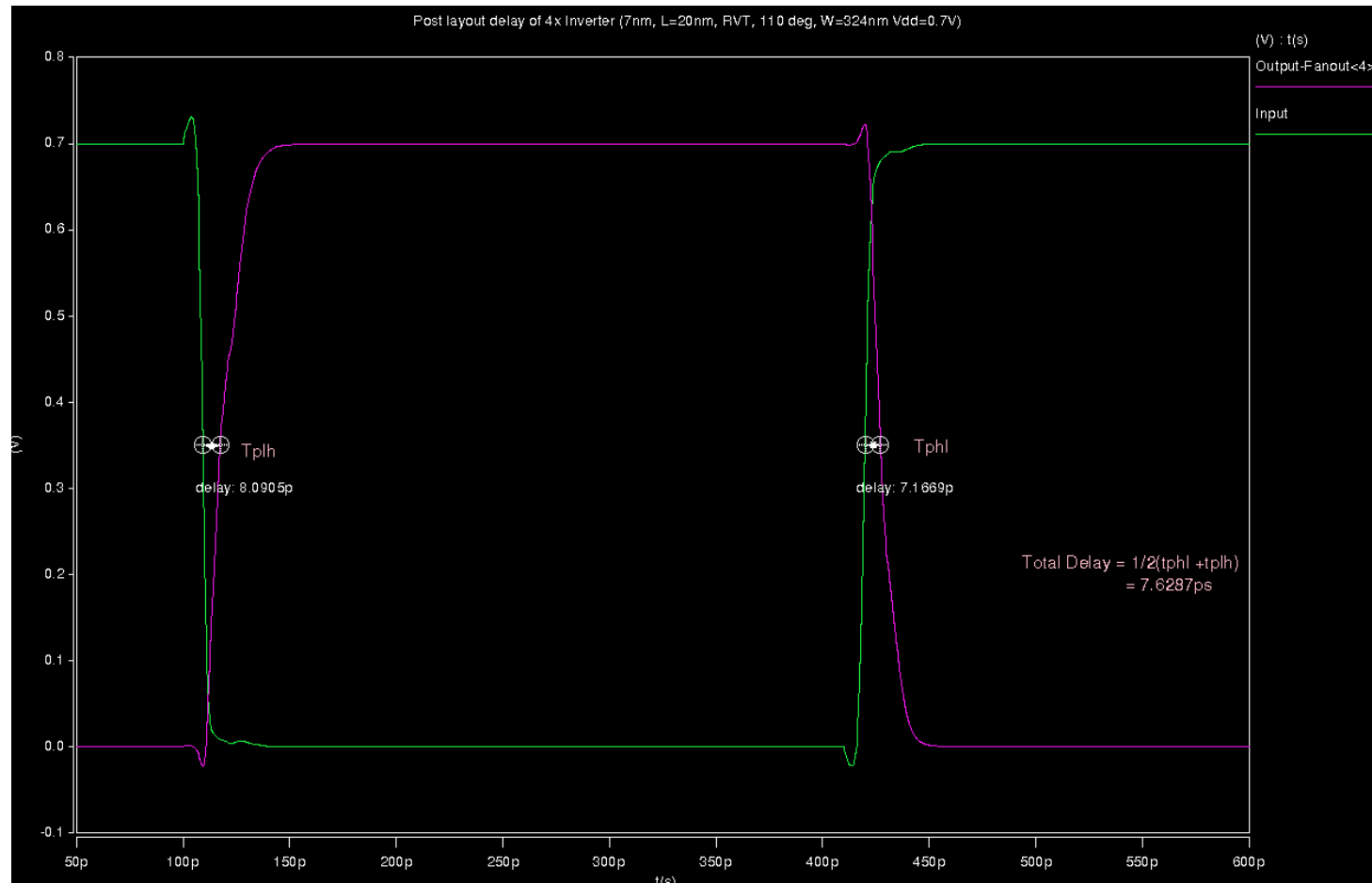


# DELAY FOR 3X INVERTER - LAYOUT

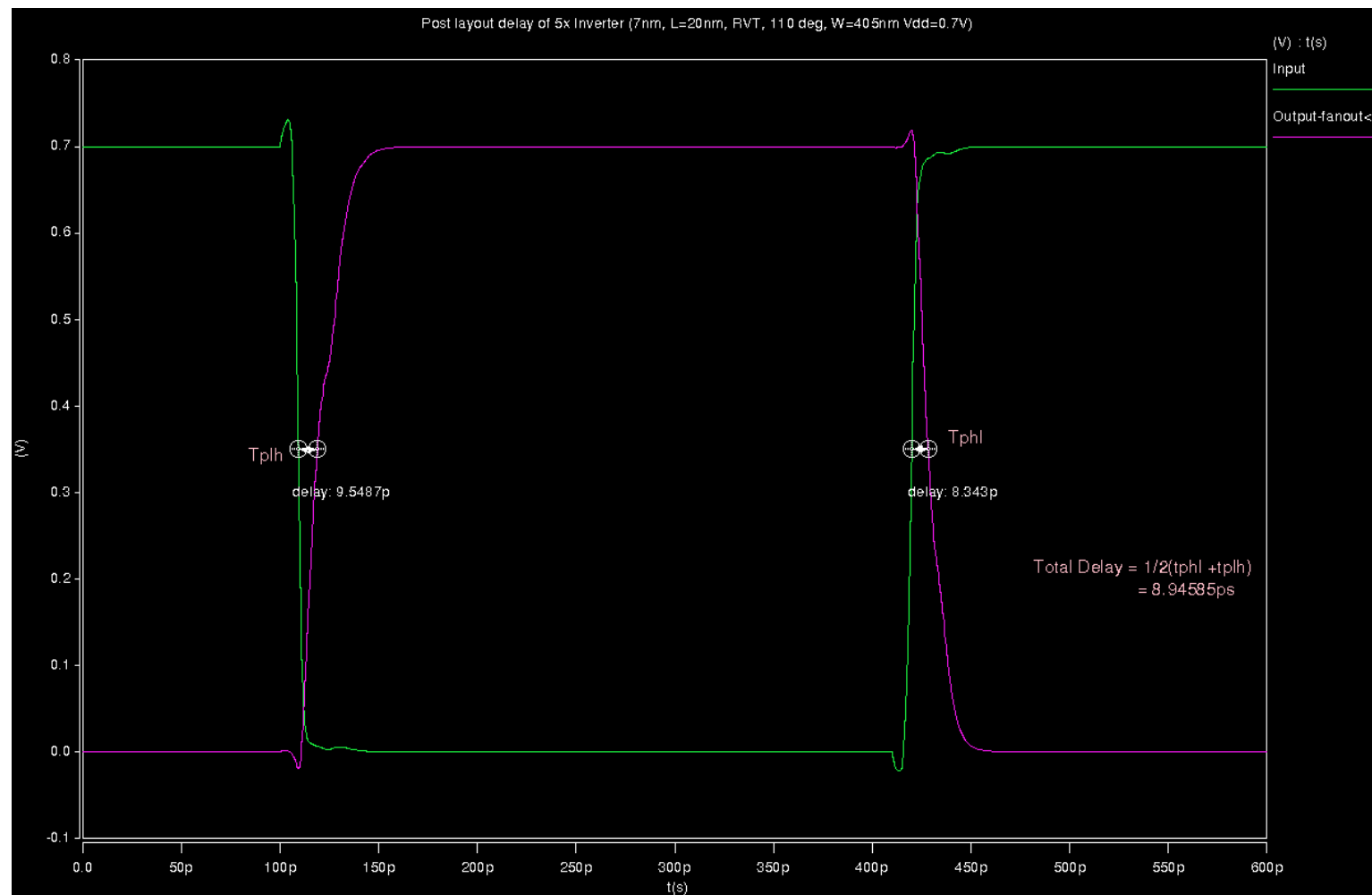




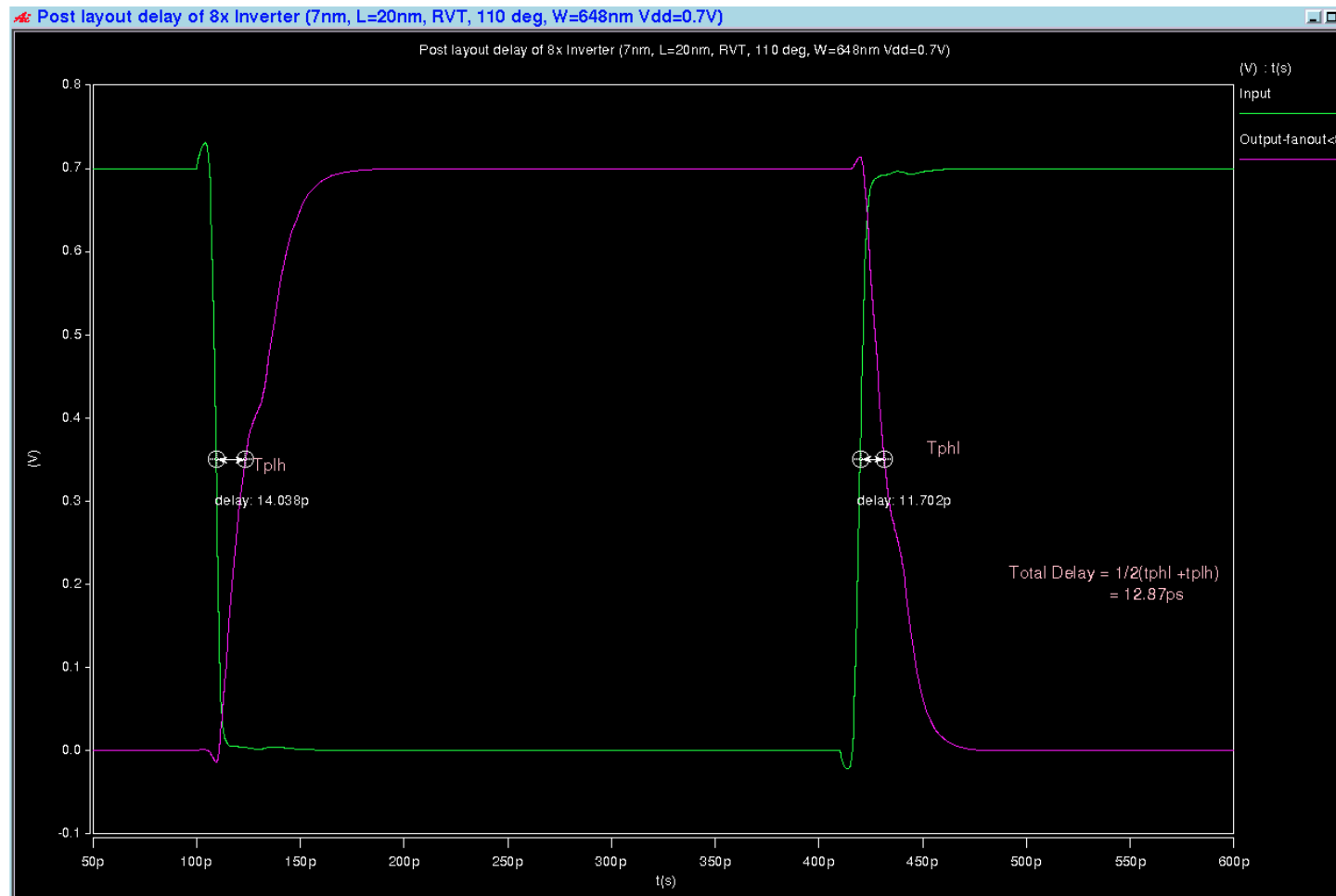
# DELAY FOR 4X INVERTER- LAYOUT



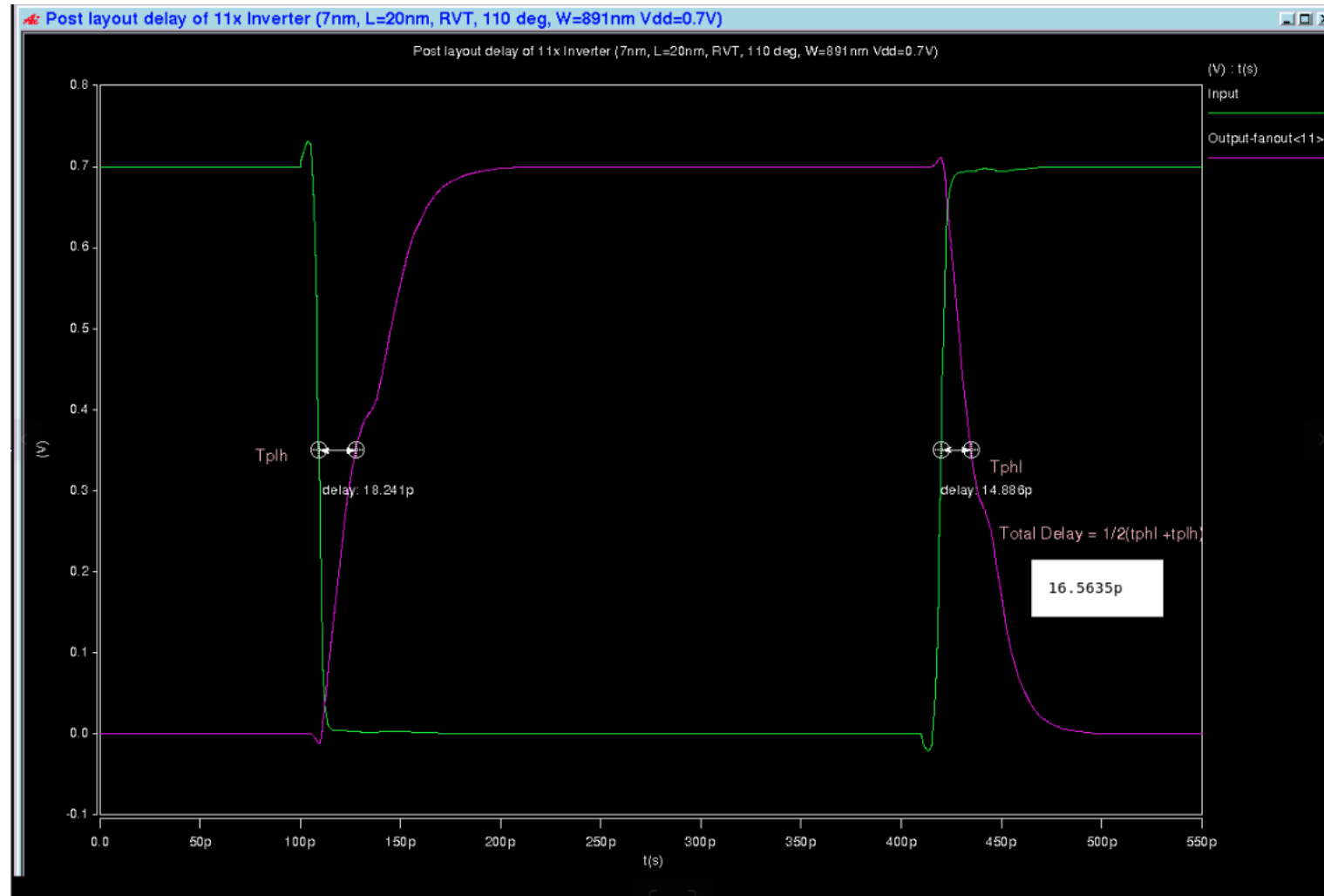
# DELAY FOR 5X INVERTER - LAYOUT



# DELAY FOR 8X INVERTER - LAYOUT



# DELAY FOR 11X INVERTER - LAYOUT



# DELAY FOR 13X INVERTER - LAYOUT

